



MSP430G2231 汽车用混合信号微控制器

1 特性

- 符合汽车应用要求
- 低电源电压范围：1.8V 至 3.6V
- 超低功耗
 - 工作模式：220 μ A（在 1MHz 频率和 2.2V 电压条件下）
 - 待机模式：0.5 μ A
 - 关闭模式（RAM 保持）：0.1 μ A
- 5 种省电模式
- 可在不到 1 μ s 的时间里从待机模式超快速唤醒
- 16 位精简指令集 (RISC) 架构，62.5ns 指令周期时间
- 基本时钟模块配置
 - 具有一个校准频率并高达 16MHz 的内部频率
 - 内部极低功率低频 (LF) 振荡器
 - 32kHz 晶振
 - 外部数字时钟源
- 具有 2 个捕捉/比较寄存器的 16 位 Timer_A
- 支持 SPI 和 I²C 的通用串行接口 (USI)
- 欠压检测器
- 具有内部基准、采样与保持以及自动扫描功能的 10 位 200ksps 模数转换器 (ADC)
- 串行板上编程，
无需外部编程电压，
利用安全熔丝实现可编程代码保护
- 具有两线制 (Spy-Bi-Wire) 接口的片上仿真逻辑电路
- 要获得系列产品成员详细信息，请参见 [Device Characteristics](#)
- 提供的封装
 - 14 引脚塑料小外形尺寸薄型封装 (TSSOP)(PW)
 - 16 引脚四方扁平无引线封装 (QFN)(RSA)
- 如需了解完整的模块说明，请参见《MSP430x2xx 系列产品用户指南》（文献编号：SLAU144）

2 应用范围

- 低成本传感器系统

3 说明

德州仪器 (TI) 的 MSP430™ 超低功耗微控制器系列由几个器件组成，这些器件针对不同应用有不同的外设集。这种架构与 5 种低功耗模式相组合，专为在便携式测量应用中延长电池使用寿命而优化。该器件具有一个强大的 16 位 RISC CPU，16 位寄存器和有助于获得最大编码效率的常数发生器。数字控制振荡器 (DCO) 可在不到 1 μ s 的时间里完成从低功耗模式至工作模式的唤醒。

MSP430G2231 器件是具有内置 16 位定时器和 10 个 I/O 引脚的超低功率混合信号微控制器。

MSP430G2231 器件有一个 10 位模数 (A/D) 转换器和使用同步协议 (SPI 或者 I²C) 的内置通信功能。配置详细信息，请参见 [Table 1](#)。

典型应用包括低成本传感器系统，此类系统负责捕捉模拟信号，将之转换为数字值，随后对数据进行处理以进行显示或传送至一个主机系统。

器件信息⁽¹⁾

订货编号	封装 (引脚)	封装尺寸
MSP430G2231IRSARQ1	RSA (16)	4mm x 4mm
MSP430G2231IPW4RQ1	PW (14)	5mm x 4.4mm

(1) 要获得最新的部件、封装和订购信息，请参阅本文档末尾的封装选项附录，或者浏览 TI 网站 www.ti.com。



4 功能方框图

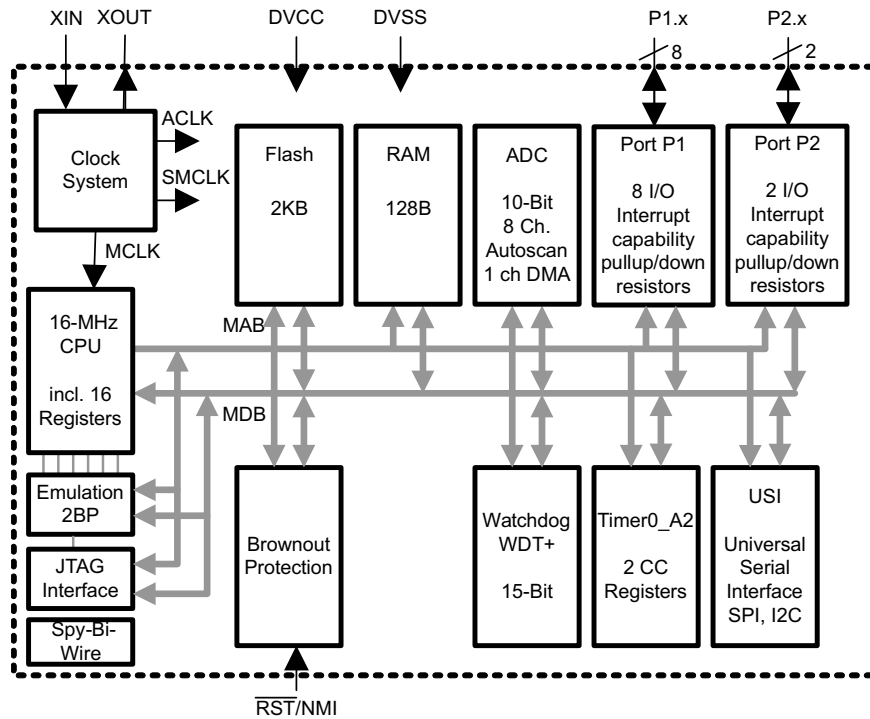


图 1. 功能方框图

目录

1	特性	1	9.18	Crystal Oscillator, Xt1, Low-Frequency Mode	25
2	应用范围	1	9.19	Internal Very-Low-Power Low-Frequency Oscillator (VLO)	25
3	说明	1	9.20	Timer_A	25
4	功能方框图	2	9.21	USI, Universal Serial Interface	26
5	修订历史记录	4	9.22	Typical Characteristics – USI Low-Level Output Voltage On SDA and SCL	26
6	Device Characteristics	4	9.23	10-Bit ADC, Power Supply and Input Range Conditions	27
7	Terminal Configuration and Functions	5	9.24	10-Bit ADC, Built-In Voltage Reference	28
7.1	14-Pin PW Package (Top View)	5	9.25	10-Bit ADC, External Reference	29
7.2	16-Pin RSA Package (Top View)	5	9.26	10-Bit ADC, Timing Parameters	29
7.3	Terminal Functions	6	9.27	10-Bit ADC, Linearity Parameters	29
8	Detailed Description	7	9.28	10-Bit ADC, Temperature Sensor and Built-In V_{MID}	30
8.1	CPU	7	9.29	Flash Memory	30
8.2	Instruction Set	7	9.30	RAM	31
8.3	Operating Modes	8	9.31	JTAG and Spy-Bi-Wire Interface	31
8.4	Interrupt Vector Addresses	9	9.32	JTAG Fuse	31
8.5	Special Function Registers (SFRs)	10	10	I/O Port Schematics	32
8.6	Memory Organization	11	10.1	Port P1 Pin Schematic: P1.0 To P1.2, Input/Output With Schmitt Trigger	32
8.7	Flash Memory	11	10.2	Port P1 Pin Schematic: P1.3, Input/Output With Schmitt Trigger	34
8.8	Peripherals	12	10.3	Port P1 Pin Schematic: P1.4, Input/Output With Schmitt Trigger	35
9	Specifications	16	10.4	Port P1 Pin Schematic: P1.5, Input/Output With Schmitt Trigger	36
9.1	Absolute Maximum Ratings	16	10.5	Port P1 Pin Schematic: P1.6, Input/Output With Schmitt Trigger	37
9.2	Recommended Operating Conditions	16	10.6	Port P1 Pin Schematic: P1.7, Input/Output With Schmitt Trigger	38
9.3	Active Mode Supply Current Into V_{CC} Excluding External Current	17	10.7	Port P2 Pin Schematic: P2.6, Input/Output With Schmitt Trigger	39
9.4	Typical Characteristics – Active Mode Supply Current (Into V_{CC})	17	10.8	Port P2 Pin Schematic: P2.7, Input/Output With Schmitt Trigger	40
9.5	Low-Power Mode Supply Currents (Into V_{CC}) Excluding External Current	18	11	器件和文档支持	41
9.6	Typical Characteristics, Low-Power Mode Supply Currents	18	11.1	器件支持	41
9.7	Schmitt-Trigger Inputs – Ports Px	19	11.2	文档支持	43
9.8	Leakage Current – Ports Px	19	11.3	Community Resources	43
9.9	Outputs – Ports Px	19	11.4	商标	44
9.10	Output Frequency – Ports Px	19	11.5	静电放电警告	44
9.11	Typical Characteristics – Outputs	20	11.6	Glossary	44
9.12	POR, BOR	21	12	机械封装和可订购信息	44
9.13	Main DCO Characteristics	23			
9.14	DCO Frequency	23			
9.15	Calibrated DCO Frequencies – Tolerance	24			
9.16	Wakeup From Lower-Power Modes (LPM3, LPM4) – Electrical Characteristics	24			
9.17	Typical Characteristics – DCO Clock Wakeup Time From LPM3, LPM4	24			

MSP430G2231-Q1

ZHCS351B –NOVEMBER 2011–REVISED MARCH 2014

www.ti.com.cn

5 修订历史记录

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

修订版本	说明
SLAS787	产品预览发布
SLAS787A	生产数据发布
SLAS787B	在整个文档内更改格式和文档结构。 已删除与 105°C 下运行有关的所有信息。 已删除针对 MSP430G2231 之外的全部器件变量。 已更新 器件和文档支持 和 机械封装和可订购信息。

6 Device Characteristics

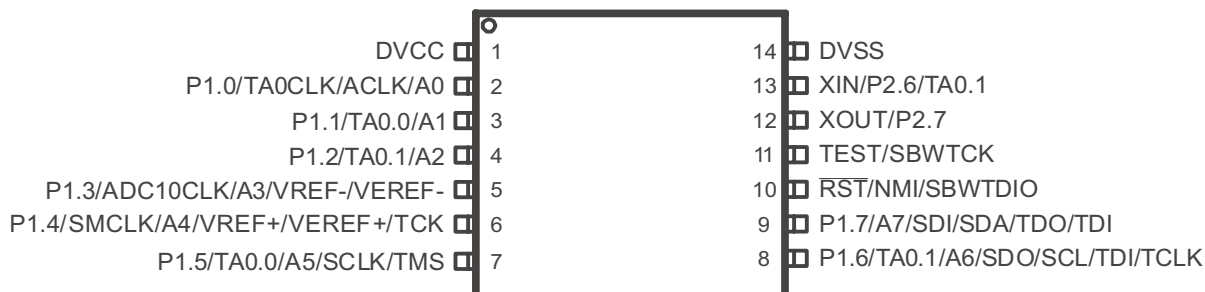
[Table 1](#) shows the features of the MSP430G2231 device.

Table 1. Family Members

Device	BSL	EEM	Flash (KB)	RAM (B)	Timer_A	USI	ADC10 Channel	Clock	I/O	Package Type
MSP430G2231	-	1	2	128	1x TA2	1	8	LF, DCO, VLO	10	16-QFN 14-TSSOP

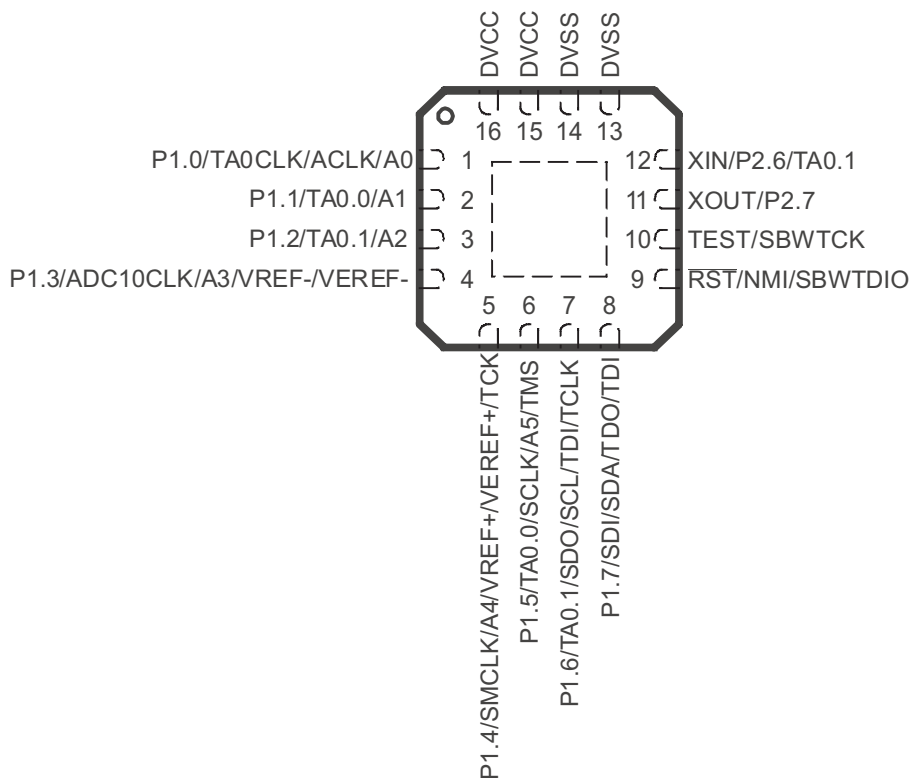
7 Terminal Configuration and Functions

7.1 14-Pin PW Package (Top View)



NOTE: See port schematics in [I/O Port Schematics](#) for detailed I/O information.

7.2 16-Pin RSA Package (Top View)



NOTE: See port schematics in [I/O Port Schematics](#) for detailed I/O information.

7.3 Terminal Functions

Table 2. Terminal Functions

TERMINAL			I/O	DESCRIPTION
NAME	NO.			
	PW	RSA		
P1.0/ TA0CLK/ ACLK/ A0	2	1	I/O	General-purpose digital I/O pin Timer0_A, clock signal TACLK input ACLK signal output ADC10 analog input A0
P1.1/ TA0.0/ A1	3	2	I/O	General-purpose digital I/O pin Timer0_A, capture: CCI0A input, compare: Out0 output ADC10 analog input A1
P1.2/ TA0.1/ A2	4	3	I/O	General-purpose digital I/O pin Timer0_A, capture: CCI1A input, compare: Out1 output ADC10 analog input A2
P1.3/ ADC10CLK/ A3/ VREF-/VEREF	5	4	I/O	General-purpose digital I/O pin ADC10, conversion clock output ADC10 analog input A3 ADC10 negative reference voltage
P1.4/ SMCLK/ A4/ VREF+/VEREF+/ TCK	6	5	I/O	General-purpose digital I/O pin SMCLK signal output ADC10 analog input A4 ADC10 positive reference voltage JTAG test clock, input terminal for device programming and test
P1.5/ TA0.0/ A5/ SCLK/ TMS	7	6	I/O	General-purpose digital I/O pin Timer0_A, compare: Out0 output ADC10 analog input A5 USI: clock input in I2C mode; clock input/output in SPI mode JTAG test mode select, input terminal for device programming and test
P1.6/ TA0.1/ A6/ SDO/ SCL/ TDI/TCLK	8	7	I/O	General-purpose digital I/O pin Timer0_A, capture: CCI1A input, compare: Out1 output ADC10 analog input A6 USI: Data output in SPI mode USI: I2C clock in I2C mode JTAG test data input or test clock input during programming and test
P1.7/ A7/ SDI/ SDA/ TDO/TDI ⁽¹⁾	9	8	I/O	General-purpose digital I/O pin ADC10 analog input A7 USI: Data input in SPI mode USI: I2C data in I2C mode JTAG test data output terminal or test data input during programming and test
XIN/ P2.6/ TA0.1	13	12	I/O	Input terminal of crystal oscillator General-purpose digital I/O pin Timer0_A, compare: Out1 output
XOUT/ P2.7	12	11	I/O	Output terminal of crystal oscillator ⁽²⁾ General-purpose digital I/O pin
RST/ NMI/ SBWTDIO	10	9	I	Reset Nonmaskable interrupt input Spy-Bi-Wire test data input/output during programming and test
TEST/ SBWTCK	11	10	I	Selects test mode for JTAG pins on Port 1. The device protection fuse is connected to TEST. Spy-Bi-Wire test clock input during programming and test
DVCC	1	15, 16	NA	Supply voltage
DVSS	14	13, 14	NA	Ground reference
QFN Pad	-	Pad	NA	QFN package pad connection to V _{SS} recommended.

(1) TDO or TDI is selected via JTAG instruction.

(2) If XOUT/P2.7 is used as an input, excess current flows until P2SEL.7 is cleared. This is due to the oscillator output driver connection to this pad after reset.

8 Detailed Description

8.1 CPU

The MSP430 CPU has a 16-bit RISC architecture that is highly transparent to the application. All operations, other than program-flow instructions, are performed as register operations in conjunction with seven addressing modes for source operand and four addressing modes for destination operand.

The CPU is integrated with 16 registers that provide reduced instruction execution time. The register-to-register operation execution time is one cycle of the CPU clock.

Four of the registers, R0 to R3, are dedicated as program counter, stack pointer, status register, and constant generator, respectively. The remaining registers are general-purpose registers.

Peripherals are connected to the CPU using data, address, and control buses, and can be handled with all instructions.

The instruction set consists of the original 51 instructions with three formats and seven address modes and additional instructions for the expanded address range. Each instruction can operate on word and byte data.

8.2 Instruction Set

The instruction set consists of 51 instructions with three formats and seven address modes. Each instruction can operate on word and byte data. [Table 3](#) shows examples of the three types of instruction formats, and [Table 4](#) shows the address modes.

Instruction Set (continued)

Program Counter	PC/R0
Stack Pointer	SP/R1
Status Register	SR/CG1/R2
Constant Generator	CG2/R3
General-Purpose Register	R4
General-Purpose Register	R5
General-Purpose Register	R6
General-Purpose Register	R7
General-Purpose Register	R8
General-Purpose Register	R9
General-Purpose Register	R10
General-Purpose Register	R11
General-Purpose Register	R12
General-Purpose Register	R13
General-Purpose Register	R14
General-Purpose Register	R15

Table 3. Instruction Word Formats

INSTRUCTION FORMAT	SYNTAX	OPERATION
Dual operands, source-destination	ADD R4,R5	R4 + R5 --> R5
Single operands, destination only	CALL R8	PC -->(TOS), R8--> PC
Relative jump, un/conditional	JNE	Jump-on-equal bit = 0

Table 4. Address Mode Descriptions⁽¹⁾

ADDRESS MODE	S	D	SYNTAX	EXAMPLE	OPERATION
Register	✓	✓	MOV Rs,Rd	MOV R10,R11	R10 -- --> R11
Indexed	✓	✓	MOV X(Rn),Y(Rm)	MOV 2(R5),6(R6)	M(2+R5) -- --> M(6+R6)
Symbolic (PC relative)	✓	✓	MOV EDE,TONI		M(EDEx) -- --> M(TONI)
Absolute	✓	✓	MOV &MEM,&TCDAT		M(MEM) -- --> M(TCDAT)
Indirect	✓		MOV @Rn,Y(Rm)	MOV @R10,Tab(R6)	M(R10) -- --> M(Tab+R6)
Indirect autoincrement	✓		MOV @Rn+,Rm	MOV @R10+,R11	M(R10) -- --> R11 R10 + 2 -- --> R10
Immediate	✓		MOV #X,TONI	MOV #45,TONI	#45 -- --> M(TONI)

(1) S = source, D = destination

8.3 Operating Modes

The MSP430 has one active mode and five software selectable low-power modes of operation. An interrupt event can wake up the device from any of the low-power modes, service the request, and restore back to the low-power mode on return from the interrupt program.

The following six operating modes can be configured by software:

- Active mode (AM)
 - All clocks are active
- Low-power mode 0 (LPM0)
 - CPU is disabled
 - ACLK and SMCLK remain active, MCLK is disabled
- Low-power mode 1 (LPM1)
 - CPU is disabled
 - ACLK and SMCLK remain active, MCLK is disabled
 - DCO's dc generator is disabled if DCO not used in active mode
- Low-power mode 2 (LPM2)
 - CPU is disabled
 - MCLK and SMCLK are disabled
 - DCO's dc generator remains enabled
 - ACLK remains active
- Low-power mode 3 (LPM3)
 - CPU is disabled
 - MCLK and SMCLK are disabled
 - DCO's dc generator is disabled
 - ACLK remains active
- Low-power mode 4 (LPM4)
 - CPU is disabled
 - ACLK is disabled
 - MCLK and SMCLK are disabled
 - DCO's dc generator is disabled
 - Crystal oscillator is stopped

8.4 Interrupt Vector Addresses

The interrupt vectors and the power-up starting address are located in the address range 0FFFFh to 0FFC0h. The vector contains the 16-bit address of the appropriate interrupt handler instruction sequence.

If the reset vector (located at address 0FFFEh) contains 0FFFFh (for example, flash is not programmed) the CPU goes into LPM4 immediately after power-up.

Table 5. Interrupt Sources, Flags, and Vectors

INTERRUPT SOURCE	INTERRUPT FLAG	SYSTEM INTERRUPT	WORD ADDRESS	PRIORITY
Power-Up External Reset Watchdog Timer+ Flash key violation PC out-of-range ⁽¹⁾	PORIFG RSTIFG WDTIFG KEYV ⁽²⁾	Reset	0FFFEh	31, highest
NMI Oscillator fault Flash memory access violation	NMIIFG OFIFG ACCVIFG ⁽²⁾⁽³⁾	(non)-maskable (non)-maskable (non)-maskable	0FFFCCh	30
			0FFFAh	29
			0FFF8h	28
			0FFF6h	27
Watchdog Timer+	WDTIFG	maskable	0FFF4h	26
Timer_A2	TACCR0 CCIFG ⁽⁴⁾	maskable	0FFF2h	25
Timer_A2	TACCR1 CCIFG, TAIFG ⁽²⁾⁽⁴⁾	maskable	0FFF0h	24
			0FFEEh	23
			0FFECCh	22
ADC10	ADC10IFG ⁽⁴⁾⁽⁵⁾	maskable	0FFEAh	21
USI	USIIFG, USISTTIFG ⁽²⁾⁽⁴⁾	maskable	0FFE8h	20
I/O Port P2 (two flags)	P2IFG.6 to P2IFG.7 ⁽²⁾⁽⁴⁾	maskable	0FFE6h	19
I/O Port P1 (eight flags)	P1IFG.0 to P1IFG.7 ⁽²⁾⁽⁴⁾	maskable	0FFE4h	18
			0FFE2h	17
			0FFE0h	16
See ⁽⁶⁾			0FFDEh to 0FFC0h	15 to 0, lowest

(1) A reset is generated if the CPU tries to fetch instructions from within the module register memory address range (0h to 01FFh) or from within unused address ranges.

(2) Multiple source flags

(3) (non)-maskable: the individual interrupt-enable bit can disable an interrupt event, but the general interrupt enable cannot.

(4) Interrupt flags are located in the module.

(5) MSP430G2x31 only

(6) The interrupt vectors at addresses 0FFDEh to 0FFC0h are not used in this device and can be used for regular program code if necessary.

8.5 Special Function Registers (SFRs)

Most interrupt and module enable bits are collected into the lowest address space. Special function register bits not allocated to a functional purpose are not physically present in the device. Simple software access is provided with this arrangement.

Legend	rw:	Bit can be read and written.
	rw-0,1:	Bit can be read and written. It is reset or set by PUC.
	rw-(0,1):	Bit can be read and written. It is reset or set by POR.
		SFR bit is not present in device.

Table 6. Interrupt Enable Register 1 and 2

Address	7	6	5	4	3	2	1	0
00h			ACCVIE	NMIIE			OFIE	WDTIE
			rw-0	rw-0			rw-0	rw-0

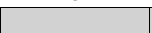
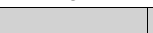
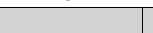
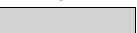
WDTIE Watchdog Timer interrupt enable. Inactive if watchdog mode is selected. Active if Watchdog Timer is configured in interval timer mode.
OFIE Oscillator fault interrupt enable
NMIIE (Non)maskable interrupt enable
ACCVIE Flash access violation interrupt enable

Address	7	6	5	4	3	2	1	0
01h								

Table 7. Interrupt Flag Register 1 and 2

Address	7	6	5	4	3	2	1	0
02h				NMIIFG	RSTIFG	PORIFG	OFIFG	WDTIFG
				rw-0	rw-(0)	rw-(1)	rw-1	rw-(0)

WDTIFG Set on watchdog timer overflow (in watchdog mode) or security key violation. Reset on V_{CC} power-on or a reset condition at the RST/NMI pin in reset mode.
OFIFG Flag set on oscillator fault.
PORIFG Power-On Reset interrupt flag. Set on V_{CC} power-up.
RSTIFG External reset interrupt flag. Set on a reset condition at RST/NMI pin in reset mode. Reset on V_{CC} power-up.
NMIIFG Set via RST/NMI pin

Address	7	6	5	4	3	2	1	0
03h								

8.6 Memory Organization

Table 8. Memory Organization

		MSP430G2231
Memory Main: interrupt vector Main: code memory	Size Flash Flash	2KB 0xFFFF to 0xFFC0 0xFFFF to 0xF800
Information memory	Size Flash	256 Byte 010FFh to 01000h
RAM	Size	128B 027Fh to 0200h
Peripherals	16-bit 8-bit 8-bit SFR	01FFh to 0100h 0FFh to 010h 0Fh to 00h

8.7 Flash Memory

The flash memory can be programmed using the Spy-Bi-Wire or JTAG port or in-system by the CPU. The CPU can perform single-byte and single-word writes to the flash memory. Features of the flash memory include:

- Flash memory has n segments of main memory and four segments of information memory (A to D) of 64 bytes each. Each segment in main memory is 512 bytes in size.
- Segments 0 to n may be erased in one step, or each segment may be individually erased.
- Segments A to D can be erased individually or as a group with segments 0 to n. Segments A to D are also called *information memory*.
- Segment A contains calibration data. After reset segment A is protected against programming and erasing. It can be unlocked but care should be taken not to erase this segment if the device-specific calibration data is required.

8.8 Peripherals

Peripherals are connected to the CPU through data, address, and control buses and can be handled using all instructions. For complete module descriptions, see the *MSP430x2xx Family User's Guide* (SLAU144).

8.8.1 Oscillator and System Clock

The clock system is supported by the basic clock module that includes support for a 32768-Hz watch crystal oscillator, an internal very-low-power low-frequency oscillator and an internal digitally controlled oscillator (DCO). The basic clock module is designed to meet the requirements of both low system cost and low power consumption. The internal DCO provides a fast turn-on clock source and stabilizes in less than 1 μ s. The basic clock module provides the following clock signals:

- Auxiliary clock (ACLK), sourced either from a 32768-Hz watch crystal or the internal LF oscillator.
- Main clock (MCLK), the system clock used by the CPU.
- Sub-Main clock (SMCLK), the sub-system clock used by the peripheral modules.

Table 9. DCO Calibration Data (Provided From Factory In Flash Information Memory Segment A)

DCO FREQUENCY	CALIBRATION REGISTER	SIZE	ADDRESS
1 MHz	CALBC1_1MHZ	byte	010FFh
	CALDCO_1MHZ	byte	010FEh

8.8.2 Brownout

The brownout circuit is implemented to provide the proper internal reset signal to the device during power on and power off.

8.8.3 Digital I/O

There is one 8-bit I/O port implemented—port P1—and two bits of I/O port P2:

- All individual I/O bits are independently programmable.
- Any combination of input, output, and interrupt condition is possible.
- Edge-selectable interrupt input capability for all the eight bits of port P1 and the two bits of port P2.
- Read/write access to port-control registers is supported by all instructions.
- Each I/O has an individually programmable pull-up/pull-down resistor.

8.8.4 WDT+ Watchdog Timer

The primary function of the watchdog timer (WDT+) module is to perform a controlled system restart after a software problem occurs. If the selected time interval expires, a system reset is generated. If the watchdog function is not needed in an application, the module can be disabled or configured as an interval timer and can generate interrupts at selected time intervals.

8.8.5 Timer_A2

Timer_A2 is a 16-bit timer/counter with two capture/compare registers. Timer_A2 can support multiple capture/compares, PWM outputs, and interval timing. Timer_A2 also has extensive interrupt capabilities. Interrupts may be generated from the counter on overflow conditions and from each of the capture/compare registers.

Table 10. Timer_A2 Signal Connections – Device With ADC10

INPUT PIN NUMBER		DEVICE INPUT SIGNAL	MODULE INPUT NAME	MODULE BLOCK	MODULE OUTPUT SIGNAL	OUTPUT PIN NUMBER	
PW	RSA					PW	RSA
2 - P1.0	1 - P1.0	TACLK	TACLK	Timer	NA		
		ACLK	ACLK				
		SMCLK	SMCLK				
2 - P1.0	1 - P1.0	TACLK	INCLK				
3 - P1.1	2 - P1.1	TA0	CCI0A	CCR0	TA0	3 - P1.1	2 - P1.1
		ACLK (internal)	CCI0B			7 - P1.5	6 - P1.5
		VSS	GND				
		VCC	VCC				
4 - P1.2	3 - P1.2	TA1	CCI1A	CCR1	TA1	4 - P1.2	3 - P1.2
8 - P1.6	7 - P1.6	TA1	CCI1B			8 - P1.6	7 - P1.6
		VSS	GND			13 - P2.6	12 - P2.6
		VCC	VCC				

8.8.6 USI

The universal serial interface (USI) module is used for serial data communication and provides the basic hardware for synchronous communication protocols like SPI and I2C.

8.8.7 ADC10

The ADC10 module supports fast, 10-bit analog-to-digital conversions. The module implements a 10-bit SAR core, sample select control, reference generator and data transfer controller, or DTC, for automatic conversion result handling, allowing ADC samples to be converted and stored without any CPU intervention.

8.8.8 Peripheral File Map

Table 11. Peripherals With Word Access

MODULE	REGISTER DESCRIPTION	REGISTER NAME	OFFSET
ADC10	ADC data transfer start address	ADC10SA	1BCh
	ADC control 0	ADC10CTL0	01B0h
	ADC control 1	ADC10CTL0	01B2h
	ADC memory	ADC10MEM	01B4h
Timer_A	Capture/compare register	TACCR1	0174h
	Capture/compare register	TACCR0	0172h
	Timer_A register	TAR	0170h
	Capture/compare control	TACCTL1	0164h
	Capture/compare control	TACCTL0	0162h
	Timer_A control	TACTL	0160h
	Timer_A interrupt vector	TAIV	012Eh
Flash Memory	Flash control 3	FCTL3	012Ch
	Flash control 2	FCTL2	012Ah
	Flash control 1	FCTL1	0128h
Watchdog Timer+	Watchdog/timer control	WDTCTL	0120h

Table 12. Peripherals With Byte Access

MODULE	REGISTER DESCRIPTION	REGISTER NAME	OFFSET
ADC10	ADC analog enable	ADC10AE0	04Ah
	ADC data transfer control 1	ADC10DTC1	049h
	ADC data transfer control 0	ADC10DTC0	048h
USI	USI control 0	USICTL0	078h
	USI control 1	USICTL1	079h
	USI clock control	USICKCTL	07Ah
	USI bit counter	USICNT	07Bh
	USI shift register	USISR	07Ch
Basic Clock System+	Basic clock system control 3	BCSCTL3	053h
	Basic clock system control 2	BCSCTL2	058h
	Basic clock system control 1	BCSCTL1	057h
	DCO clock frequency control	DCOCTL	056h
Port P2	Port P2 resistor enable	P2REN	02Fh
	Port P2 selection	P2SEL	02Eh
	Port P2 interrupt enable	P2IE	02Dh
	Port P2 interrupt edge select	P2IES	02Ch
	Port P2 interrupt flag	P2IFG	02Bh
	Port P2 direction	P2DIR	02Ah
	Port P2 output	P2OUT	029h
	Port P2 input	P2IN	028h

Table 12. Peripherals With Byte Access (continued)

MODULE	REGISTER DESCRIPTION	REGISTER NAME	OFFSET
Port P1	Port P1 resistor enable	P1REN	027h
	Port P1 selection	P1SEL	026h
	Port P1 interrupt enable	P1IE	025h
	Port P1 interrupt edge select	P1IES	024h
	Port P1 interrupt flag	P1IFG	023h
	Port P1 direction	P1DIR	022h
	Port P1 output	P1OUT	021h
	Port P1 input	P1IN	020h
Special Function	SFR interrupt flag 2	IFG2	003h
	SFR interrupt flag 1	IFG1	002h
	SFR interrupt enable 2	IE2	001h
	SFR interrupt enable 1	IE1	000h

9 Specifications

9.1 Absolute Maximum Ratings ⁽¹⁾

Voltage applied at V_{CC} to V_{SS}		–0.3 V to 4.1 V
Voltage applied to any pin ⁽²⁾		–0.3 V to $V_{CC} + 0.3$ V
Diode current at any device pin		±2 mA
Storage temperature range, T_{stg} ⁽³⁾	Unprogrammed device	–55°C to 150°C
	Programmed device	–55°C to 150°C

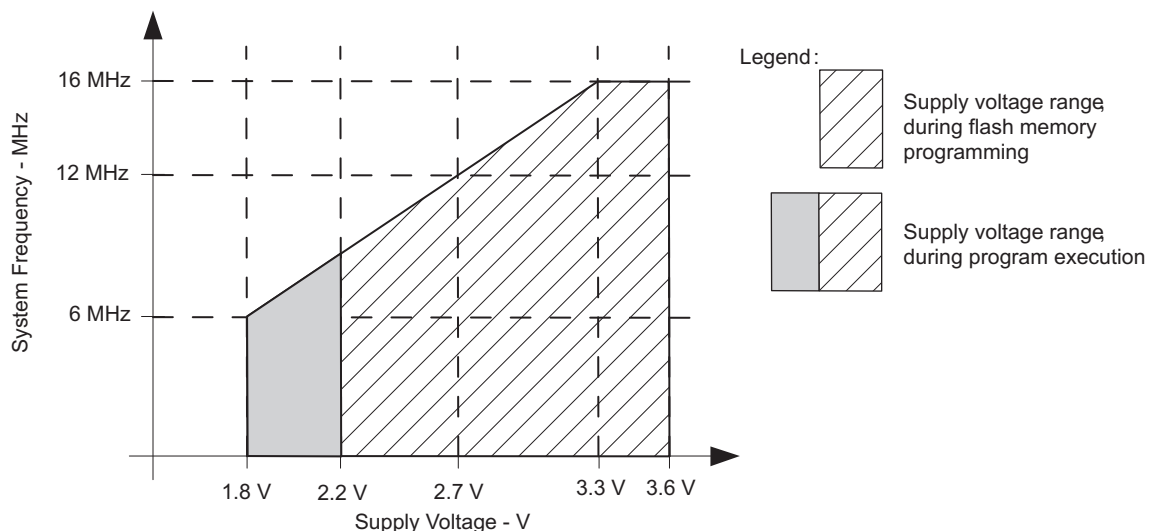
- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltages referenced to V_{SS} . The JTAG fuse-blow voltage, V_{FB} , is allowed to exceed the absolute maximum rating. The voltage is applied to the TEST pin when blowing the JTAG fuse.
- (3) Higher temperature may be applied during board soldering according to the current JEDEC J-STD-020 specification with peak reflow temperatures not higher than classified on the device label on the shipping boxes or reels.

9.2 Recommended Operating Conditions

Typical values are specified at $V_{CC} = 3.3$ V and $T_A = 25^\circ\text{C}$ (unless otherwise noted)

			MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	During program execution	1.8		3.6	V
		During flash programming	2.2		3.6	
V _{SS}	Supply voltage			0		V
T _A	Operating free-air temperature	I version	−40		85	°C
f _{SYSTEM}	Processor frequency (maximum MCLK frequency) ⁽¹⁾⁽²⁾	V _{CC} = 1.8 V, Duty cycle = 50% ± 10%	dc		6	MHz
		V _{CC} = 2.7 V, Duty cycle = 50% ± 10%	dc		12	
		V _{CC} = 3.3 V, Duty cycle = 50% ± 10%	dc		16	

- (1) The MSP430 CPU is clocked directly with MCLK. Both the high and low phase of MCLK must not exceed the pulse width of the specified maximum frequency.
- (2) Modules might have a different maximum input clock specification. See the specification of the respective module in this data sheet.



Note: Minimum processor frequency is defined by system clock. Flash program or erase operations require a minimum V_{CC} of 2.2 V.

Figure 2. Safe Operating Area

9.3 Active Mode Supply Current Into V_{CC} Excluding External Current

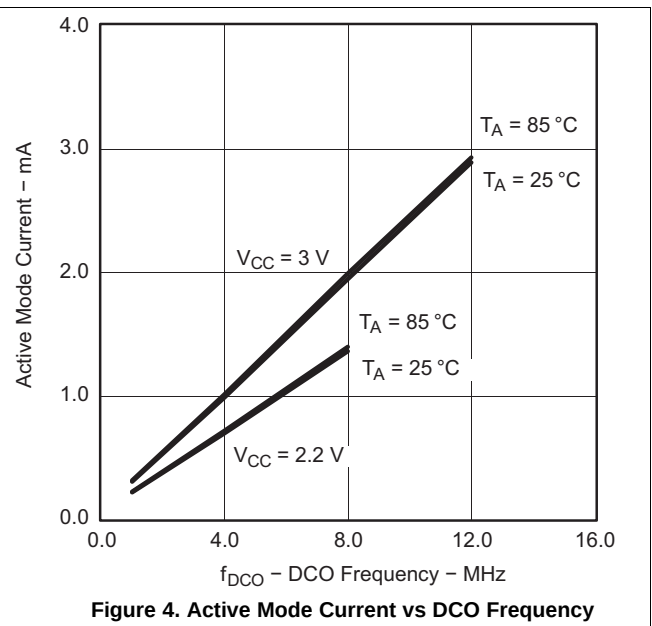
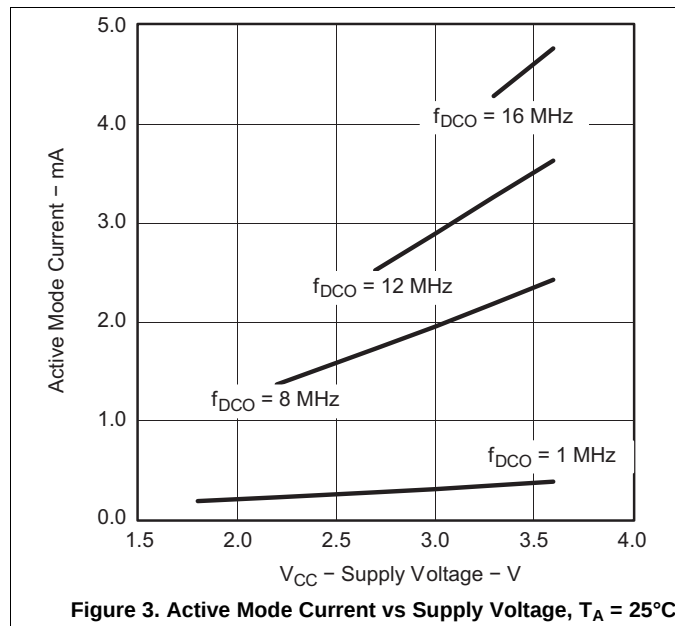
over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)⁽¹⁾⁽²⁾

PARAMETER	TEST CONDITIONS	T_A	V_{CC}	MIN	TYP	MAX	UNIT
$I_{AM,1MHz}$ Active mode (AM) current (1 MHz)	$f_{DCO} = f_{MCLK} = f_{SMCLK} = 1\text{ MHz}$, $f_{ACLK} = 32768\text{ Hz}$, Program executes in flash, $BCSCTL1 = CALBC1_1MHz$, $DCOCTL = CALDCO_1MHz$, $CPUOFF = 0$, $SCG0 = 0$, $SCG1 = 0$, $OSCOFF = 0$		2.2 V		220		μA
			3 V		300	370	

(1) All inputs are tied to 0 V or to V_{CC} . Outputs do not source or sink any current.

(2) The currents are characterized with a Micro Crystal CC4V-T1A SMD crystal with a load capacitance of 9 pF. The internal and external load capacitance is chosen to closely match the required 9 pF.

9.4 Typical Characteristics – Active Mode Supply Current (Into V_{CC})



9.5 Low-Power Mode Supply Currents (Into V_{CC}) Excluding External Current

 over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)^{(1) (2)}

PARAMETER	TEST CONDITIONS	T_A	V_{CC}	MIN	TYP	MAX	UNIT
$I_{LPM0,1MHz}$ Low-power mode 0 (LPM0) current ⁽³⁾	$f_{MCLK} = 0$ MHz, $f_{SMCLK} = f_{DCO} = 1$ MHz, $f_{ACLK} = 32768$ Hz, BCSCTL1 = CALBC1_1MHZ, DCOCTL = CALDCO_1MHZ, CPUOFF = 1, SCG0 = 0, SCG1 = 0, OSCOFF = 0	25°C	2.2 V		65		μA
I_{LPM2} Low-power mode 2 (LPM2) current ⁽⁴⁾	$f_{MCLK} = f_{SMCLK} = 0$ MHz, $f_{DCO} = 1$ MHz, $f_{ACLK} = 32768$ Hz, BCSCTL1 = CALBC1_1MHZ, DCOCTL = CALDCO_1MHZ, CPUOFF = 1, SCG0 = 0, SCG1 = 1, OSCOFF = 0	25°C	2.2 V		22		μA
$I_{LPM3,LFXT1}$ Low-power mode 3 (LPM3) current ⁽⁴⁾	$f_{DCO} = f_{MCLK} = f_{SMCLK} = 0$ MHz, $f_{ACLK} = 32768$ Hz, CPUOFF = 1, SCG0 = 1, SCG1 = 1, OSCOFF = 0	25°C	2.2 V		0.7	1.5	μA
$I_{LPM3,VLO}$ Low-power mode 3 current, (LPM3) ⁽⁴⁾	$f_{DCO} = f_{MCLK} = f_{SMCLK} = 0$ MHz, f_{ACLK} from internal LF oscillator (VLO), CPUOFF = 1, SCG0 = 1, SCG1 = 1, OSCOFF = 0	25°C	2.2 V		0.5	0.7	μA
I_{LPM4} Low-power mode 4 (LPM4) current ⁽⁵⁾	$f_{DCO} = f_{MCLK} = f_{SMCLK} = 0$ MHz, $f_{ACLK} = 0$ Hz, CPUOFF = 1, SCG0 = 1, SCG1 = 1, OSCOFF = 1	25°C	2.2 V		0.1	0.5	μA
		85°C	2.2 V		0.8	1.5	μA

 (1) All inputs are tied to 0 V or to V_{CC} . Outputs do not source or sink any current.

(2) The currents are characterized with a Micro Crystal CC4V-T1A SMD crystal with a load capacitance of 9 pF.

(3) Current for brownout and WDT clocked by SMCLK included.

(4) Current for brownout and WDT clocked by ACLK included.

(5) Current for brownout included.

9.6 Typical Characteristics, Low-Power Mode Supply Currents

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

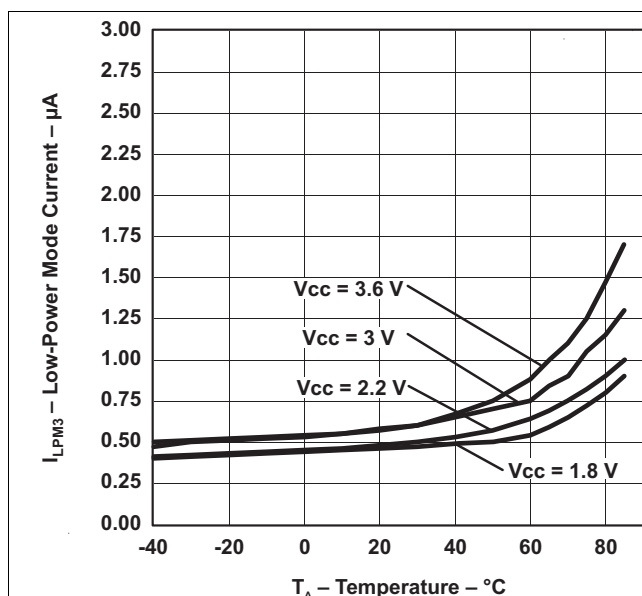


Figure 5. LPM3 Current vs Temperature

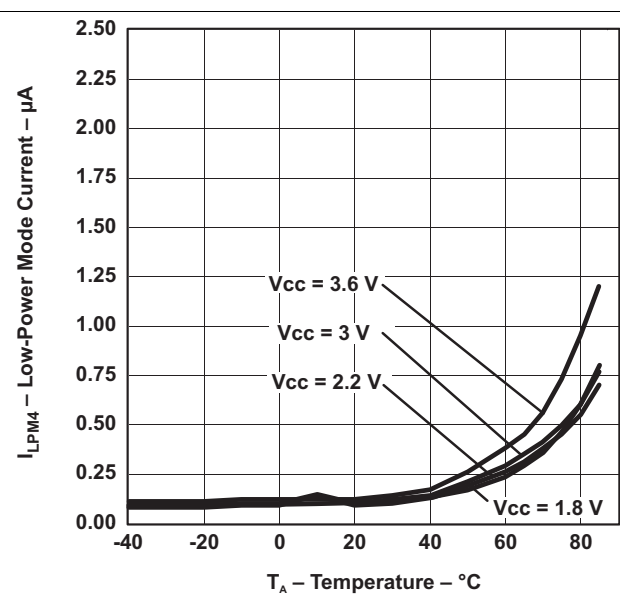


Figure 6. LPM4 Current vs Temperature

9.7 Schmitt-Trigger Inputs – Ports Px

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
V _{IT+} Positive-going input threshold voltage			0.45 V _{CC}		0.75 V _{CC}	V
		3 V	1.35		2.25	
V _{IT–} Negative-going input threshold voltage			0.25 V _{CC}		0.55 V _{CC}	V
		3 V	0.75		1.65	
V _{hys} Input voltage hysteresis (V _{IT+} – V _{IT–})		3 V	0.3		1	V
R _{Pull} Pullup/pulldown resistor	For pullup: V _{IN} = V _{SS} For pulldown: V _{IN} = V _{CC}	3 V	20	35	50	kΩ
C _I Input capacitance	V _{IN} = V _{SS} or V _{CC}			5		pF

9.8 Leakage Current – Ports Px

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	MAX	UNIT
I _{lkg(Px,y)} High-impedance leakage current	(1) (2)	3 V		±50	nA

- (1) The leakage current is measured with V_{SS} or V_{CC} applied to the corresponding pin(s), unless otherwise noted.
(2) The leakage of the digital port pins is measured individually. The port pin is selected for input and the pullup/pulldown resistor is disabled.

9.9 Outputs – Ports Px

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
V _{OH} High-level output voltage	I _(OHmax) = –6 mA ⁽¹⁾	3 V		V _{CC} – 0.3		V
V _{OL} Low-level output voltage	I _(OLmax) = 6 mA ⁽¹⁾	3 V		V _{SS} + 0.3		V

- (1) The maximum total current, I_(OHmax) and I_(OLmax), for all outputs combined should not exceed ±48 mA to hold the maximum voltage drop specified.

9.10 Output Frequency – Ports Px

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
f _{Px,y} Port output frequency (with load)	Px.y, C _L = 20 pF, R _L = 1 kΩ ⁽¹⁾ (2)	3 V		12		MHz
f _{Port_CLK} Clock output frequency	Px.y, C _L = 20 pF ⁽²⁾	3 V		16		MHz

- (1) A resistive divider with 2 × 0.5 kΩ between V_{CC} and V_{SS} is used as load. The output is connected to the center tap of the divider.
(2) The output voltage reaches at least 10% and 90% V_{CC} at the specified toggle frequency.

9.11 Typical Characteristics – Outputs

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

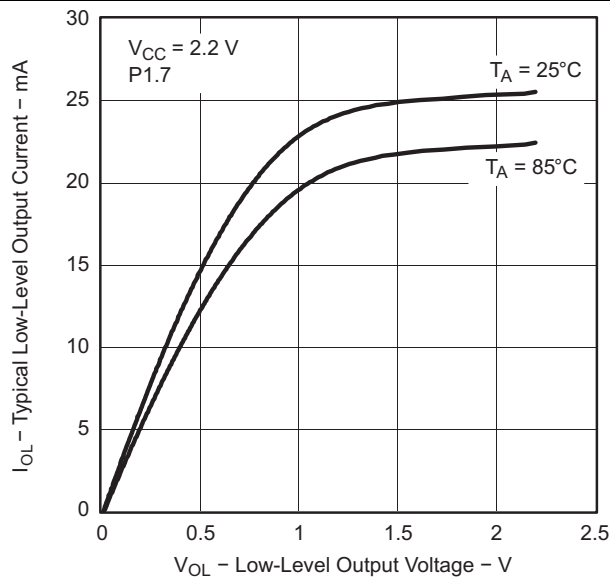


Figure 7. Typical Low-Level Output Current vs Low-Level Output Voltage

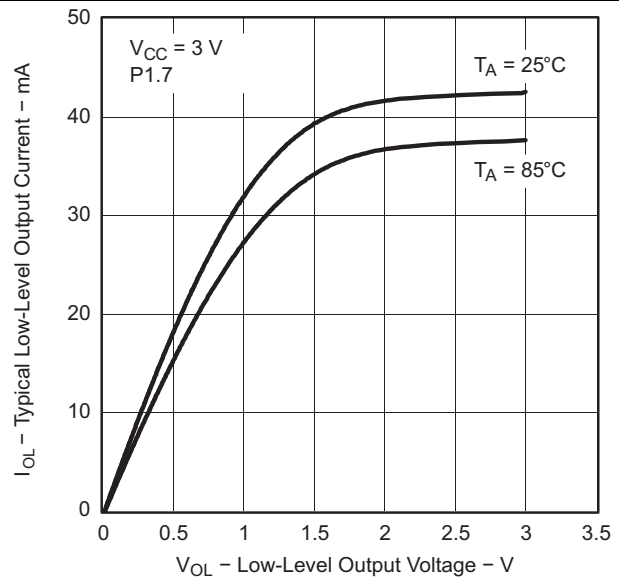


Figure 8. Typical Low-Level Output Current vs Low-Level Output Voltage

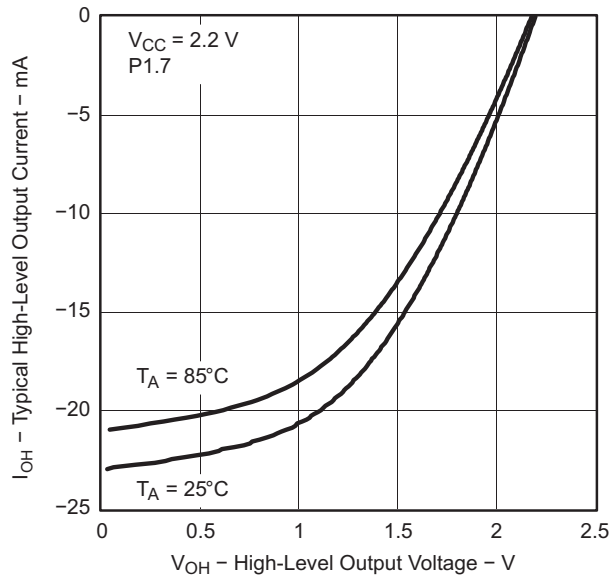


Figure 9. Typical High-Level Output Current vs High-Level Output Voltage

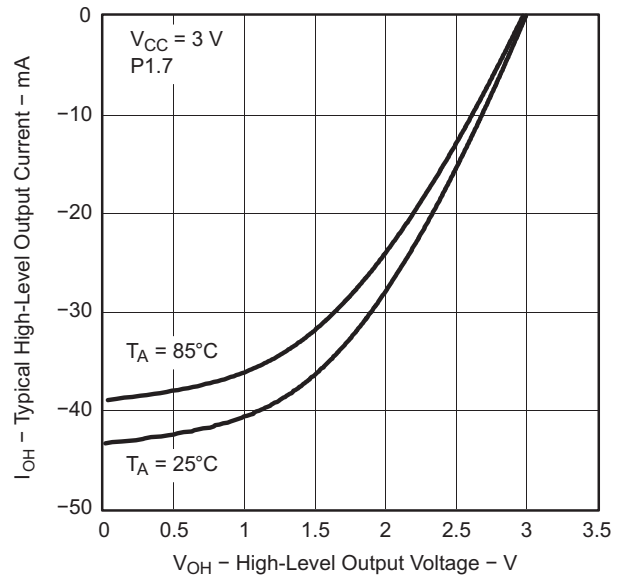


Figure 10. Typical High-Level Output Current vs High-Level Output Voltage

9.12 POR, BOR⁽¹⁾⁽²⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
V _{CC(start)}	See Figure 11	dV _{CC} /dt ≤ 3 V/s		0.7 × V _(B_IT-)		V
V _(B_IT-)	See Figure 11 through Figure 13	dV _{CC} /dt ≤ 3 V/s		1.35		V
V _{hys(B_IT-)}	See Figure 11	dV _{CC} /dt ≤ 3 V/s		130		mV
t _{d(BOR)}	See Figure 11				2000	μs
t _(reset)	Pulse duration needed at $\overline{\text{RST}}/\text{NMI}$ pin to accepted reset internally	2.2 V, 3 V	2			μs

- (1) The current consumption of the brownout module is already included in the I_{CC} current consumption data. The voltage level V_(B_IT-) + V_{hys(B_IT-)} is ≤ 1.8 V.
- (2) During power up, the CPU begins code execution following a period of t_{d(BOR)} after V_{CC} = V_(B_IT-) + V_{hys(B_IT-)}. The default DCO settings must not be changed until V_{CC} ≥ V_{CC(min)}, where V_{CC(min)} is the minimum supply voltage for the desired operating frequency.

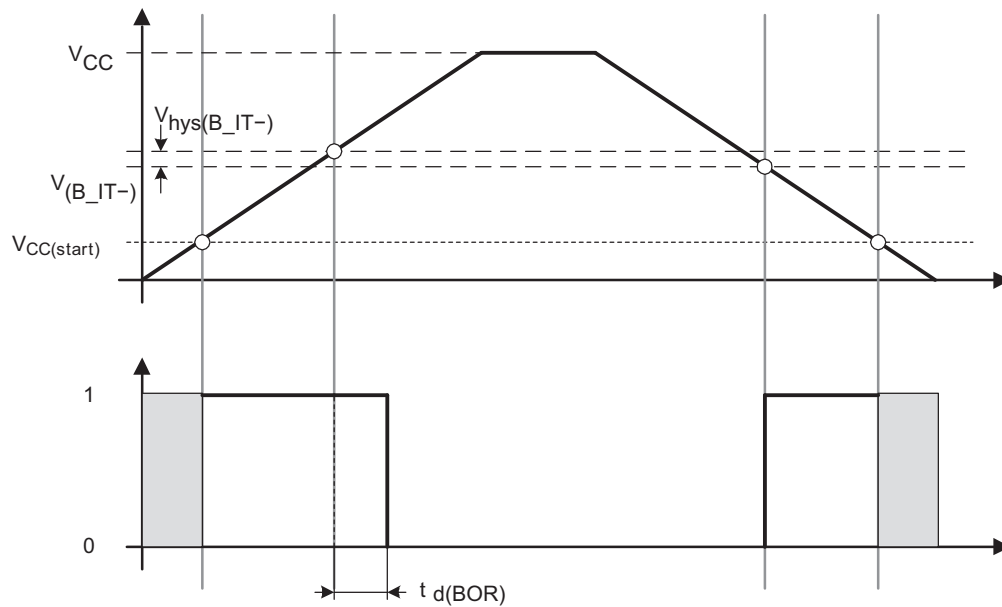


Figure 11. POR and BOR vs Supply Voltage

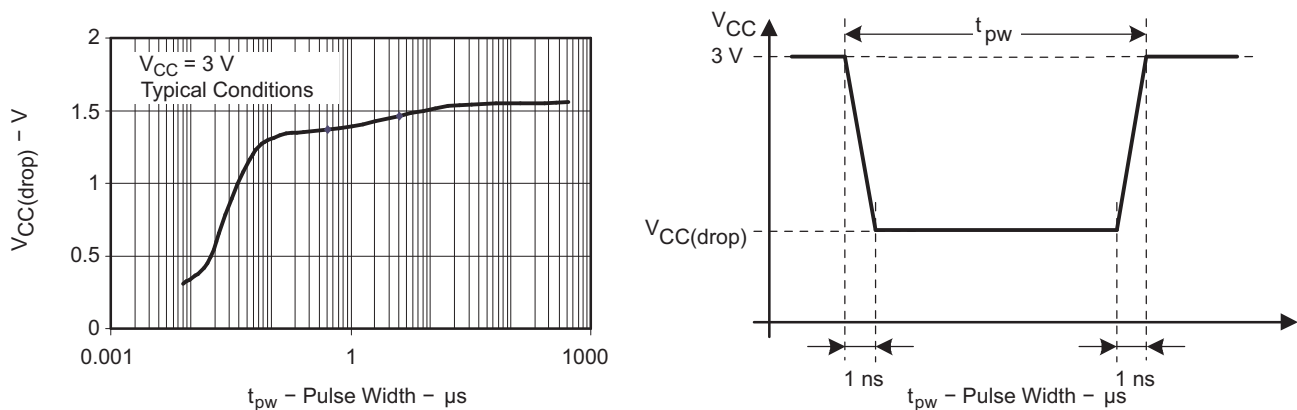


Figure 12. V_{CC(drop)} Level With a Square Voltage Drop to Generate a POR or BOR Signal

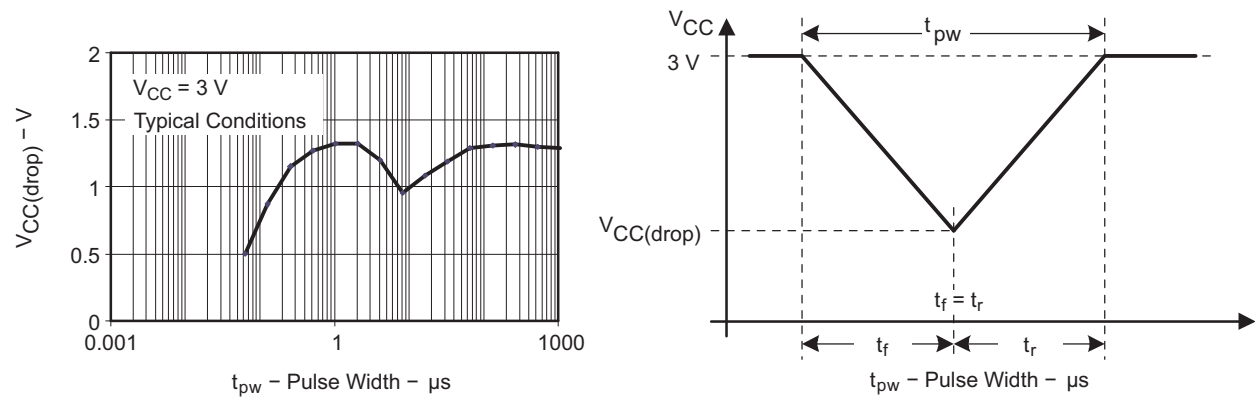


Figure 13. $V_{CC(drop)}$ Level With a Triangle Voltage Drop to Generate a POR or BOR Signal

9.13 Main DCO Characteristics

- All ranges selected by RSELx overlap with RSELx + 1: RSELx = 0 overlaps RSELx = 1, ... RSELx = 14 overlaps RSELx = 15.
- DCO control bits DCOx have a step size as defined by parameter S_{DCO}.
- Modulation control bits MODx select how often f_{DCO(RSEL,DCO+1)} is used within the period of 32 DCOCLK cycles. The frequency f_{DCO(RSEL,DCO)} is used for the remaining cycles. The frequency is an average equal to:

$$f_{\text{average}} = \frac{32 \times f_{\text{DCO(RSEL,DCO)}} \times f_{\text{DCO(RSEL,DCO+1)}}}{\text{MOD} \times f_{\text{DCO(RSEL,DCO)}} + (32 - \text{MOD}) \times f_{\text{DCO(RSEL,DCO+1)}}}$$

9.14 DCO Frequency

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
V _{CC}	Supply voltage	RSELx < 14		1.8		3.6	V
		RSELx = 14		2.2		3.6	V
		RSELx = 15		3		3.6	V
f _{DCO(0,0)}	DCO frequency (0, 0)	RSELx = 0, DCOx = 0, MODx = 0	3 V	0.06		0.14	MHz
f _{DCO(0,3)}	DCO frequency (0, 3)	RSELx = 0, DCOx = 3, MODx = 0	3 V		0.12		MHz
f _{DCO(1,3)}	DCO frequency (1, 3)	RSELx = 1, DCOx = 3, MODx = 0	3 V		0.15		MHz
f _{DCO(2,3)}	DCO frequency (2, 3)	RSELx = 2, DCOx = 3, MODx = 0	3 V		0.21		MHz
f _{DCO(3,3)}	DCO frequency (3, 3)	RSELx = 3, DCOx = 3, MODx = 0	3 V		0.30		MHz
f _{DCO(4,3)}	DCO frequency (4, 3)	RSELx = 4, DCOx = 3, MODx = 0	3 V		0.41		MHz
f _{DCO(5,3)}	DCO frequency (5, 3)	RSELx = 5, DCOx = 3, MODx = 0	3 V		0.58		MHz
f _{DCO(6,3)}	DCO frequency (6, 3)	RSELx = 6, DCOx = 3, MODx = 0	3 V		0.80		MHz
f _{DCO(7,3)}	DCO frequency (7, 3)	RSELx = 7, DCOx = 3, MODx = 0	3 V	0.8		1.5	MHz
f _{DCO(8,3)}	DCO frequency (8, 3)	RSELx = 8, DCOx = 3, MODx = 0	3 V		1.6		MHz
f _{DCO(9,3)}	DCO frequency (9, 3)	RSELx = 9, DCOx = 3, MODx = 0	3 V		2.3		MHz
f _{DCO(10,3)}	DCO frequency (10, 3)	RSELx = 10, DCOx = 3, MODx = 0	3 V		3.4		MHz
f _{DCO(11,3)}	DCO frequency (11, 3)	RSELx = 11, DCOx = 3, MODx = 0	3 V		4.25		MHz
f _{DCO(12,3)}	DCO frequency (12, 3)	RSELx = 12, DCOx = 3, MODx = 0	3 V	4.3		7.3	MHz
f _{DCO(13,3)}	DCO frequency (13, 3)	RSELx = 13, DCOx = 3, MODx = 0	3 V		7.8		MHz
f _{DCO(14,3)}	DCO frequency (14, 3)	RSELx = 14, DCOx = 3, MODx = 0	3 V	8.6		13.9	MHz
f _{DCO(15,3)}	DCO frequency (15, 3)	RSELx = 15, DCOx = 3, MODx = 0	3 V		15.25		MHz
f _{DCO(15,7)}	DCO frequency (15, 7)	RSELx = 15, DCOx = 7, MODx = 0	3 V		21		MHz
S _{RSEL}	Frequency step between range RSEL and RSEL+1	S _{RSEL} = f _{DCO(RSEL+1,DCO)} /f _{DCO(RSEL,DCO)}	3 V		1.35		ratio
S _{DCO}	Frequency step between tap DCO and DCO+1	S _{DCO} = f _{DCO(RSEL,DCO+1)} /f _{DCO(RSEL,DCO)}	3 V		1.08		ratio
	Duty cycle	Measured at SMCLK output	3 V		50		%

9.15 Calibrated DCO Frequencies – Tolerance

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	T _A	V _{CC}	MIN	TYP	MAX	UNIT
1-MHz tolerance over temperature ⁽¹⁾	BCSCTL1= CALBC1_1MHz, DCOCTL = CALDCO_1MHz, calibrated at 30°C and 3 V	0°C to 85°C -40°C to 105°C	3 V	-3	±0.5	+3	%
1-MHz tolerance over V _{CC}	BCSCTL1= CALBC1_1MHz, DCOCTL = CALDCO_1MHz, calibrated at 30°C and 3 V	30°C	1.8 V to 3.6 V	-3	±2	+3	%
1-MHz tolerance overall	BCSCTL1= CALBC1_1MHz, DCOCTL = CALDCO_1MHz, calibrated at 30°C and 3 V	-40°C to 85°C -40°C to 105°C	1.8 V to 3.6 V	-6	±3	+6	%

(1) This is the frequency change from the measured frequency at 30°C over temperature.

9.16 Wakeup From Lower-Power Modes (LPM3, LPM4) – Electrical Characteristics

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
t _{DCO,LPM3/4} DCO clock wakeup time from LPM3 or LPM4 ⁽¹⁾	BCSCTL1= CALBC1_1MHz, DCOCTL = CALDCO_1MHz	3 V		1.5		μs
t _{CPU,LPM3/4} CPU wakeup time from LPM3 or LPM4 ⁽²⁾				1/f _{MCLK} + t _{Clock,LPM3/4}		

(1) The DCO clock wakeup time is measured from the edge of an external wake-up signal (for example, port interrupt) to the first clock edge observable externally on a clock pin (MCLK or SMCLK).

(2) Parameter applicable only if DCOCLK is used for MCLK.

9.17 Typical Characteristics – DCO Clock Wakeup Time From LPM3, LPM4

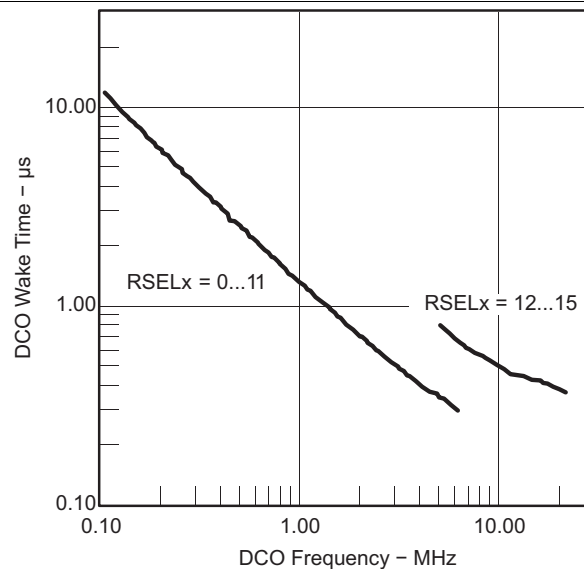


Figure 14. DCO Wakeup Time From LPM3 vs DCO Frequency

9.18 Crystal Oscillator, Xt1, Low-Frequency Mode ⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
f _{LFXT1,LF}	LFXT1 oscillator crystal frequency, LF mode 0, 1	XTS = 0, LFXT1Sx = 0 or 1	1.8 V to 3.6 V	32768			Hz
f _{LFXT1,LF,logic}	LFXT1 oscillator logic level square wave input frequency, LF mode	XTS = 0, XCAPx = 0, LFXT1Sx = 3	1.8 V to 3.6 V	10000	32768	50000	Hz
O _{A,LF}	Oscillation allowance for LF crystals	XTS = 0, LFXT1Sx = 0, f _{LFXT1,LF} = 32768 Hz, C _{L,eff} = 6 pF		500			kΩ
		XTS = 0, LFXT1Sx = 0, f _{LFXT1,LF} = 32768 Hz, C _{L,eff} = 12 pF		200			
C _{L,eff}	Integrated effective load capacitance, LF mode ⁽²⁾	XTS = 0, XCAPx = 0		1			pF
		XTS = 0, XCAPx = 1		5.5			
		XTS = 0, XCAPx = 2		8.5			
		XTS = 0, XCAPx = 3		11			
	Duty cycle, LF mode	XTS = 0, Measured at P2.0/ACLK, f _{LFXT1,LF} = 32768 Hz	2.2 V	30	50	70	%
f _{Fault,LF}	Oscillator fault frequency, LF mode ⁽³⁾	XTS = 0, XCAPx = 0, LFXT1Sx = 3 ⁽⁴⁾	2.2 V	10	10000		Hz

- (1) To improve EMI on the XT1 oscillator, the following guidelines should be observed.
 - (a) Keep the trace between the device and the crystal as short as possible.
 - (b) Design a good ground plane around the oscillator pins.
 - (c) Prevent crosstalk from other clock or data lines into oscillator pins XIN and XOUT.
 - (d) Avoid running PCB traces underneath or adjacent to the XIN and XOUT pins.
 - (e) Use assembly materials and techniques that avoid any parasitic load on the oscillator XIN and XOUT pins.
 - (f) If conformal coating is used, ensure that it does not induce capacitive or resistive leakage between the oscillator pins.
 - (g) Do not route the XOUT line to the JTAG header to support the serial programming adapter as shown in other documentation. This signal is no longer required for the serial programming adapter.
- (2) Includes parasitic bond and package capacitance (approximately 2 pF per pin).
Because the PCB adds additional capacitance, it is recommended to verify the correct load by measuring the ACLK frequency. For a correct setup, the effective load capacitance should always match the specification of the used crystal.
- (3) Frequencies below the MIN specification set the fault flag. Frequencies above the MAX specification do not set the fault flag. Frequencies in between might set the flag.
- (4) Measured with logic-level input frequency but also applies to operation with crystals.

9.19 Internal Very-Low-Power Low-Frequency Oscillator (VLO)

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		T _A	V _{CC}	MIN	TYP	MAX	UNIT
f _{VLO}	VLO frequency	-40°C to 85°C	3 V	4	12	20	kHz
df _{VLO} /dT	VLO frequency temperature drift	-40°C to 85°C	3 V		0.5		%/°C
df _{VLO} /dV _{CC}	VLO frequency supply voltage drift	25°C	1.8 V to 3.6 V		4		%/V

9.20 Timer_A

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
f _{TA}	Timer_A input clock frequency	Internal: SMCLK, ACLK External: TACLK, INCLK Duty cycle = 50% ± 10%		f _{SYSTEM}		MHz
t _{TA,cap}	Timer_A capture timing	TA0, TA1	3 V	20		ns

9.21 USI, Universal Serial Interface

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
f _{USI} USI clock frequency	External: SCLK, Duty cycle = 50% ±10%, SPI slave mode			f _{SYSTEM}		MHz
V _{OL,I2C} Low-level output voltage on SDA and SCL	USI module in I2C mode, I _{OL(max)} = 1.5 mA	3 V	V _{SS}		V _{SS} + 0.4	V

9.22 Typical Characteristics – USI Low-Level Output Voltage On SDA and SCL

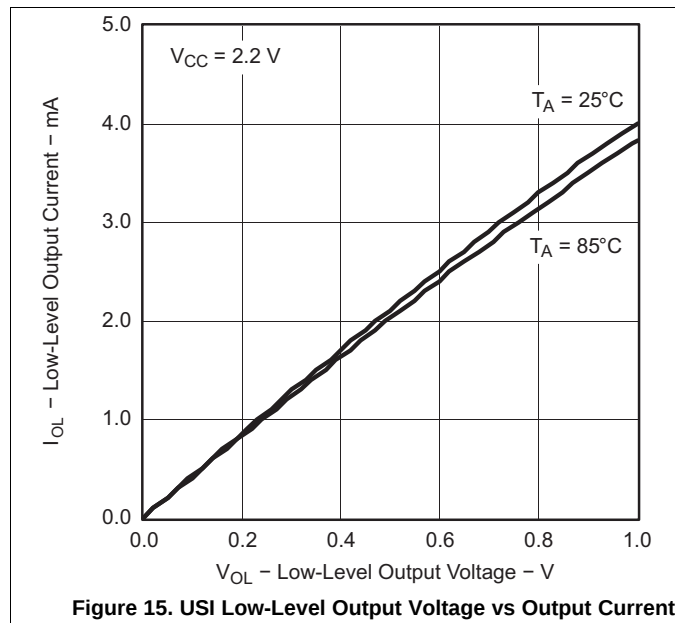


Figure 15. USI Low-Level Output Voltage vs Output Current

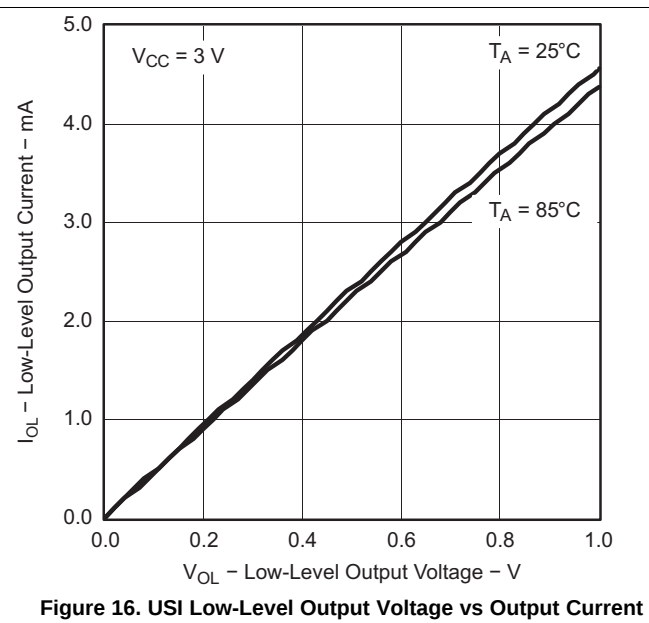


Figure 16. USI Low-Level Output Voltage vs Output Current

9.23 10-Bit ADC, Power Supply and Input Range Conditions

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)⁽¹⁾

PARAMETER	TEST CONDITIONS	T _A	V _{CC}	MIN	TYP	MAX	UNIT
V _{CC}	Analog supply voltage	V _{SS} = 0 V		2.2		3.6	V
V _{AX}	Analog input voltage ⁽²⁾	All Ax terminals, Analog inputs selected in ADC10AE register	3 V	0		V _{CC}	V
I _{ADC10}	ADC10 supply current ⁽³⁾	f _{ADC10CLK} = 5.0 MHz, ADC10ON = 1, REFON = 0, ADC10SHT0 = 1, ADC10SHT1 = 0, ADC10DIV = 0	3 V		0.6	1.2	mA
I _{REF+}	Reference supply current, reference buffer disabled ⁽⁴⁾	f _{ADC10CLK} = 5.0 MHz, ADC10ON = 0, REF2_5V = 0, REFON = 1, REFOUT = 0	3 V		0.25	0.4	mA
		f _{ADC10CLK} = 5.0 MHz, ADC10ON = 0, REF2_5V = 1, REFON = 1, REFOUT = 0			0.25	0.4	
I _{REFB,0}	Reference buffer supply current with ADC10SR = 0 ⁽⁴⁾	f _{ADC10CLK} = 5.0 MHz, ADC10ON = 0, REFON = 1, REF2_5V = 0, REFOUT = 1, ADC10SR = 0	3 V		1.1	1.4	mA
I _{REFB,1}	Reference buffer supply current with ADC10SR = 1 ⁽⁴⁾	f _{ADC10CLK} = 5.0 MHz, ADC10ON = 0, REFON = 1, REF2_5V = 0, REFOUT = 1, ADC10SR = 1	3 V		0.5	0.7	mA
C _I	Input capacitance	Only one terminal Ax can be selected at one time	3 V			27	pF
R _I	Input MUX ON resistance	0 V ≤ V _{AX} ≤ V _{CC}	3 V		1000	2000	Ω

(1) The leakage current is defined in the leakage current table with Px.y/Ax parameter.

(2) The analog input voltage range must be within the selected reference voltage range V_{R+} to V_{R-} for valid conversion results.

(3) The internal reference supply current is not included in current consumption parameter I_{ADC10}.

(4) The internal reference current is supplied via terminal V_{CC}. Consumption is independent of the ADC10ON control bit, unless a conversion is active. The REFON bit enables the built-in reference to settle before starting an A/D conversion.

9.24 10-Bit ADC, Built-In Voltage Reference

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
V _{CC,REF+}	Positive built-in reference analog supply voltage range I _{VREF+} ≤ 1 mA, REF2_5V = 0		2.2			V
	I _{VREF+} ≤ 1 mA, REF2_5V = 1		2.9			
V _{REF+}	Positive built-in reference voltage I _{VREF+} ≤ I _{VREF+max} , REF2_5V = 0	3 V	1.41	1.5	1.59	V
	I _{VREF+} ≤ I _{VREF+max} , REF2_5V = 1		2.35	2.5	2.65	
I _{LD,VREF+}	Maximum VREF+ load current	3 V			±1	mA
VREF+ load regulation	I _{VREF+} = 500 μA ± 100 μA, Analog input voltage V _{AX} ≈ 0.75 V, REF2_5V = 0	3 V			±2	LSB
	I _{VREF+} = 500 μA ± 100 μA, Analog input voltage V _{AX} ≈ 1.25 V, REF2_5V = 1				±2	
VREF+ load regulation response time	I _{VREF+} = 100 μA → 900 μA, V _{AX} ≈ 0.5 × VREF+, Error of conversion result ≤ 1 LSB, ADC10SR = 0	3 V			400	ns
C _{VREF+}	Maximum capacitance at pin VREF+	3 V			100	pF
TC _{REF+}	Temperature coefficient	3 V			±100	ppm/°C
t _{REFON}	Settling time of internal reference voltage to 99.9% VREF	3.6 V			30	μs
t _{REFBURST}	Settling time of reference buffer to 99.9% VREF	3 V			2	μs

9.25 10-Bit ADC, External Reference⁽¹⁾

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
VEREF+ Positive external reference input voltage range ⁽²⁾	VEREF+ > VREF−, SREF1 = 1, SREF0 = 0		1.4		V _{CC}	V
	VEREF− ≤ VREF+ ≤ V _{CC} − 0.15 V, SREF1 = 1, SREF0 = 1 ⁽³⁾		1.4		3	
VEREF− Negative external reference input voltage range ⁽⁴⁾	VEREF+ > VREF−		0		1.2	V
ΔVEREF Differential external reference input voltage range, ΔVEREF = VREF+ − VREF−	VEREF+ > VREF− ⁽⁵⁾		1.4		V _{CC}	V
I _{VEREF+} Static input current into VREF+	0 V ≤ VREF+ ≤ V _{CC} , SREF1 = 1, SREF0 = 0	3 V		±1		μA
	0 V ≤ VREF+ ≤ V _{CC} − 0.15 V ≤ 3 V, SREF1 = 1, SREF0 = 1 ⁽³⁾	3 V		0		
I _{VEREF−} Static input current into VREF−	0 V ≤ VREF− ≤ V _{CC}	3 V		±1		μA

- (1) The external reference is used during conversion to charge and discharge the capacitance array. The input capacitance, C_I, is also the dynamic load for an external reference during conversion. The dynamic impedance of the reference supply should follow the recommendations on analog-source impedance to allow the charge to settle for 10-bit accuracy.
- (2) The accuracy limits the minimum positive external reference voltage. Lower reference voltage levels may be applied with reduced accuracy requirements.
- (3) Under this condition the external reference is internally buffered. The reference buffer is active and requires the reference buffer supply current I_{REFB}. The current consumption can be limited to the sample and conversion period with REBURST = 1.
- (4) The accuracy limits the maximum negative external reference voltage. Higher reference voltage levels may be applied with reduced accuracy requirements.
- (5) The accuracy limits the minimum external differential reference voltage. Lower differential reference voltage levels may be applied with reduced accuracy requirements.

9.26 10-Bit ADC, Timing Parameters

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
f _{ADC10CLK} ADC10 input clock frequency	For specified performance of ADC10 linearity parameters	3 V	0.45		6.3	MHz
	ADC10SR = 0 ADC10SR = 1		0.45		1.5	
f _{ADC10OSC} ADC10 built-in oscillator frequency	ADC10DIVx = 0, ADC10SSELx = 0, f _{ADC10CLK} = f _{ADC10OSC}	3 V	3.7		6.3	MHz
t _{CONVERT} Conversion time	ADC10 built-in oscillator, ADC10SSELx = 0, f _{ADC10CLK} = f _{ADC10OSC}	3 V	2.06		3.51	μs
	f _{ADC10CLK} from ACLK, MCLK, or SMCLK, ADC10SSELx ≠ 0			13 × ADC10DIV × 1/f _{ADC10CLK}		
t _{ADC10ON} Turn-on settling time of the ADC	(1)				100	ns

- (1) The condition is that the error in a conversion started after t_{ADC10ON} is less than ±0.5 LSB. The reference and input signal are already settled.

9.27 10-Bit ADC, Linearity Parameters

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
E _I Integral linearity error		3 V			±1	LSB
E _D Differential linearity error		3 V			±1	LSB
E _O Offset error	Source impedance R _S < 100 Ω	3 V			±1	LSB
E _G Gain error		3 V		±1.1	±2	LSB
E _T Total unadjusted error		3 V		±2	±5	LSB

9.28 10-Bit ADC, Temperature Sensor and Built-In V_{MID}

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
I _{SENSOR}	Temperature sensor supply current ⁽¹⁾	REFON = 0, INCHx = 0Ah, T _A = 25°C	3 V		60		μA
TC _{SENSOR}		ADC10ON = 1, INCHx = 0Ah ⁽²⁾	3 V		3.55		mV/°C
t _{Sensor(sample)}	Sample time required if channel 10 is selected ⁽³⁾	ADC10ON = 1, INCHx = 0Ah, Error of conversion result ≤ 1 LSB	3 V	30			μs
I _{VMID}	Current into divider at channel 11	ADC10ON = 1, INCHx = 0Bh	3 V			⁽⁴⁾	μA
V _{MID}	V _{CC} divider at channel 11	ADC10ON = 1, INCHx = 0Bh, V _{MID} ≠ 0.5 × V _{CC}	3 V		1.5		V
t _{VMID(sample)}	Sample time required if channel 11 is selected ⁽⁵⁾	ADC10ON = 1, INCHx = 0Bh, Error of conversion result ≤ 1 LSB	3 V	1220			ns

- (1) The sensor current I_{SENSOR} is consumed if (ADC10ON = 1 and REFON = 1) or (ADC10ON = 1 and INCH = 0Ah and sample signal is high). When REFON = 1, I_{SENSOR} is included in I_{REF+}. When REFON = 0, I_{SENSOR} applies during conversion of the temperature sensor input (INCH = 0Ah).
- (2) The following formula can be used to calculate the temperature sensor output voltage:

$$V_{\text{Sensor,typ}} = TC_{\text{Sensor}} (273 + T [^{\circ}\text{C}]) + V_{\text{Offset,sensor}} [\text{mV}]$$
 or

$$V_{\text{Sensor,typ}} = TC_{\text{Sensor}} T [^{\circ}\text{C}] + V_{\text{Sensor}}(T_A = 0^{\circ}\text{C}) [\text{mV}]$$
- (3) The typical equivalent impedance of the sensor is 51 kΩ. The sample time required includes the sensor-on time t_{SENSOR(on)}.
- (4) No additional current is needed. The V_{MID} is used during sampling.
- (5) The on-time t_{VMID(on)} is included in the sampling time t_{VMID(sample)}; no additional on time is needed.

9.29 Flash Memory

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
V _{CC(PGM/ERASE)}	Program and erase supply voltage			2.2		3.6	V
f _{FTG}	Flash timing generator frequency			257		476	kHz
I _{PGM}	Supply current from V _{CC} during program		2.2 V, 3.6 V		1	5	mA
I _{ERASE}	Supply current from V _{CC} during erase		2.2 V, 3.6 V		1	7	mA
t _{CPT}	Cumulative program time ⁽¹⁾		2.2 V, 3.6 V			10	ms
t _{CMErase}	Cumulative mass erase time		2.2 V, 3.6 V	20			ms
	Program/erase endurance			10 ⁴	10 ⁵		cycles
t _{Retention}	Data retention duration	T _J = 25°C		15			years
t _{Word}	Word or byte program time	⁽²⁾			30		t _{FTG}
t _{Block, 0}	Block program time for first byte or word	⁽²⁾			25		t _{FTG}
t _{Block, 1-63}	Block program time for each additional byte or word	⁽²⁾			18		t _{FTG}
t _{Block, End}	Block program end-sequence wait time	⁽²⁾			6		t _{FTG}
t _{Mass Erase}	Mass erase time	⁽²⁾			10593		t _{FTG}
t _{Seg Erase}	Segment erase time	⁽²⁾			4819		t _{FTG}

- (1) The cumulative program time must not be exceeded when writing to a 64-byte flash block. This parameter applies to all programming methods: individual word/byte write and block write modes.
- (2) These values are hardwired into the Flash Controller's state machine (t_{FTG} = 1/f_{FTG}).

9.30 RAM

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
$V_{(RAMh)}$ RAM retention supply voltage ⁽¹⁾	CPU halted	1.6		V

- (1) This parameter defines the minimum supply voltage V_{CC} when the data in RAM remains unchanged. No program execution should happen during this supply voltage condition.

9.31 JTAG and Spy-Bi-Wire Interface

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	MIN	TYP	MAX	UNIT
f_{SBW} Spy-Bi-Wire input frequency		2.2 V, 3 V	0		20	MHz
$t_{SBW,Low}$ Spy-Bi-Wire low clock pulse length		2.2 V, 3 V	0.025		15	μ s
$t_{SBW,En}$ Spy-Bi-Wire enable time (TEST high to acceptance of first clock edge ⁽¹⁾)		2.2 V, 3 V			1	μ s
$t_{SBW,Ret}$ Spy-Bi-Wire return to normal operation time		2.2 V, 3 V	15		100	μ s
f_{TCK} TCK input frequency ⁽²⁾		2.2 V	0		5	MHz
		3 V	0		10	MHz
$R_{Internal}$ Internal pulldown resistance on TEST		2.2 V, 3 V	25	60	90	k Ω

- (1) Tools that access the Spy-Bi-Wire interface must wait for the maximum $t_{SBW,En}$ time after pulling the TEST/SBW TCK pin high before applying the first SBW TCK clock edge.
- (2) f_{TCK} may be restricted to meet the timing requirements of the module selected.

9.32 JTAG Fuse ⁽¹⁾

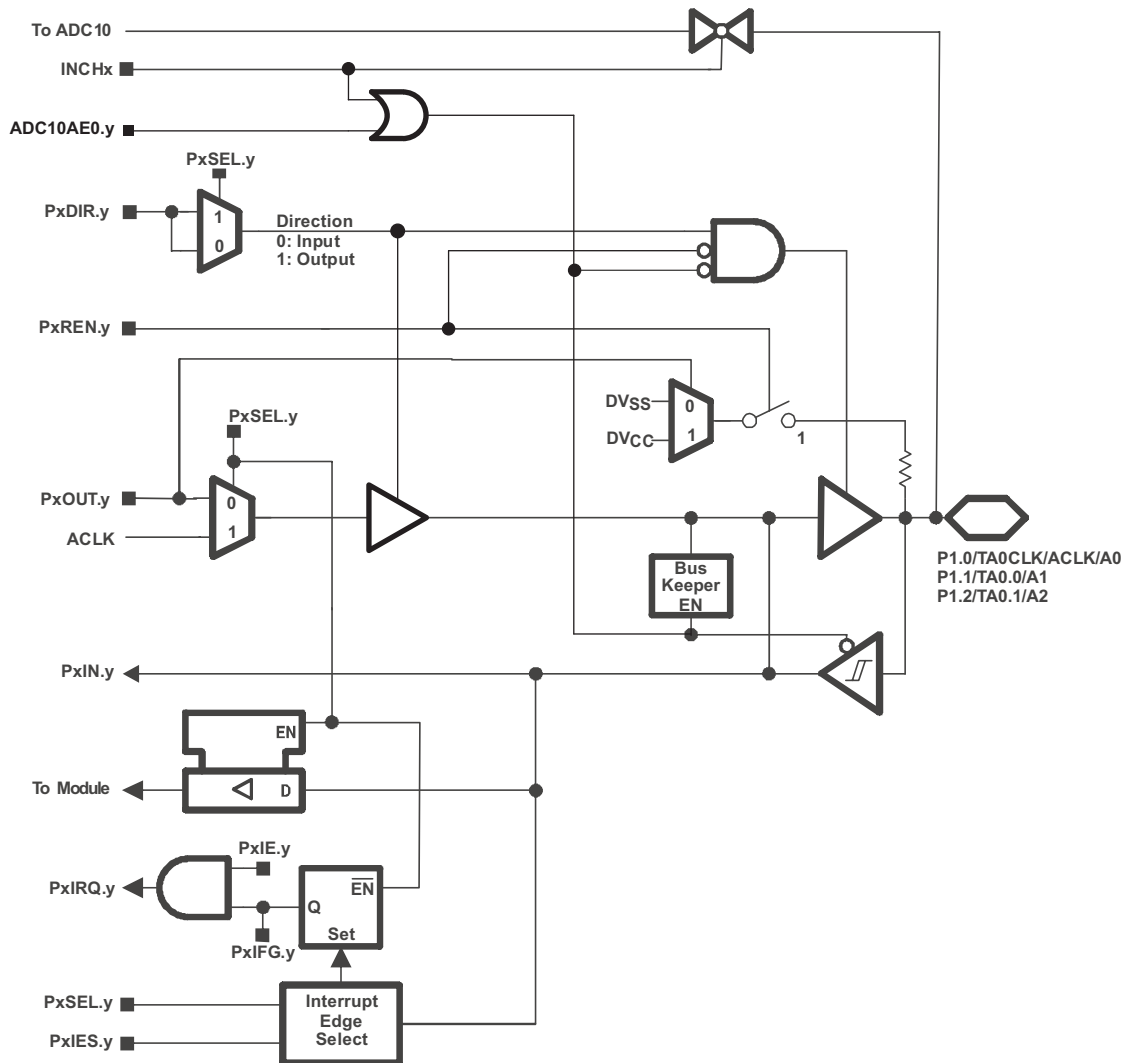
over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
$V_{CC(FB)}$ Supply voltage during fuse-blow condition	$T_A = 25^\circ\text{C}$	2.5		V
V_{FB} Voltage level on TEST for fuse blow		6	7	V
I_{FB} Supply current into TEST during fuse blow			100	mA
t_{FB} Time to blow fuse			1	ms

- (1) Once the fuse is blown, no further access to the JTAG/Test, Spy-Bi-Wire, and emulation feature is possible, and JTAG is switched to bypass mode.

10 I/O Port Schematics

10.1 Port P1 Pin Schematic: P1.0 To P1.2, Input/Output With Schmitt Trigger



Port P1 Pin Schematic: P1.0 To P1.2, Input/Output With Schmitt Trigger (continued)
Table 13. Port P1 (P1.0 To P1.2) Pin Functions

PIN NAME (P1.x)	x	FUNCTION	CONTROL BITS OR SIGNALS		
			P1DIR.x	P1SEL.x	ADC10AE.x (INCH.y = 1)
P1.0/ TA0CLK/ ACLK/ A0	0	P1.x (I/O)	I: 0; O: 1	0	0
		TA0.TACLK	0	1	0
		ACLK	1	1	0
		A0	X	X	1 (y = 0)
P1.1/ TA0.0/ A1	1	P1.x (I/O)	I: 0; O: 1	0	0
		TA0.0	1	1	0
		TA0.CCI0A	0	1	0
		A1	X	X	1 (y = 1)
P1.2/ TA0.1/ A2/	2	P1.x (I/O)	I: 0; O: 1	0	0
		TA0.1	1	1	0
		TA0.CCI1A	0	1	0
		A2	X	X	1 (y = 2)

10.2 Port P1 Pin Schematic: P1.3, Input/Output With Schmitt Trigger

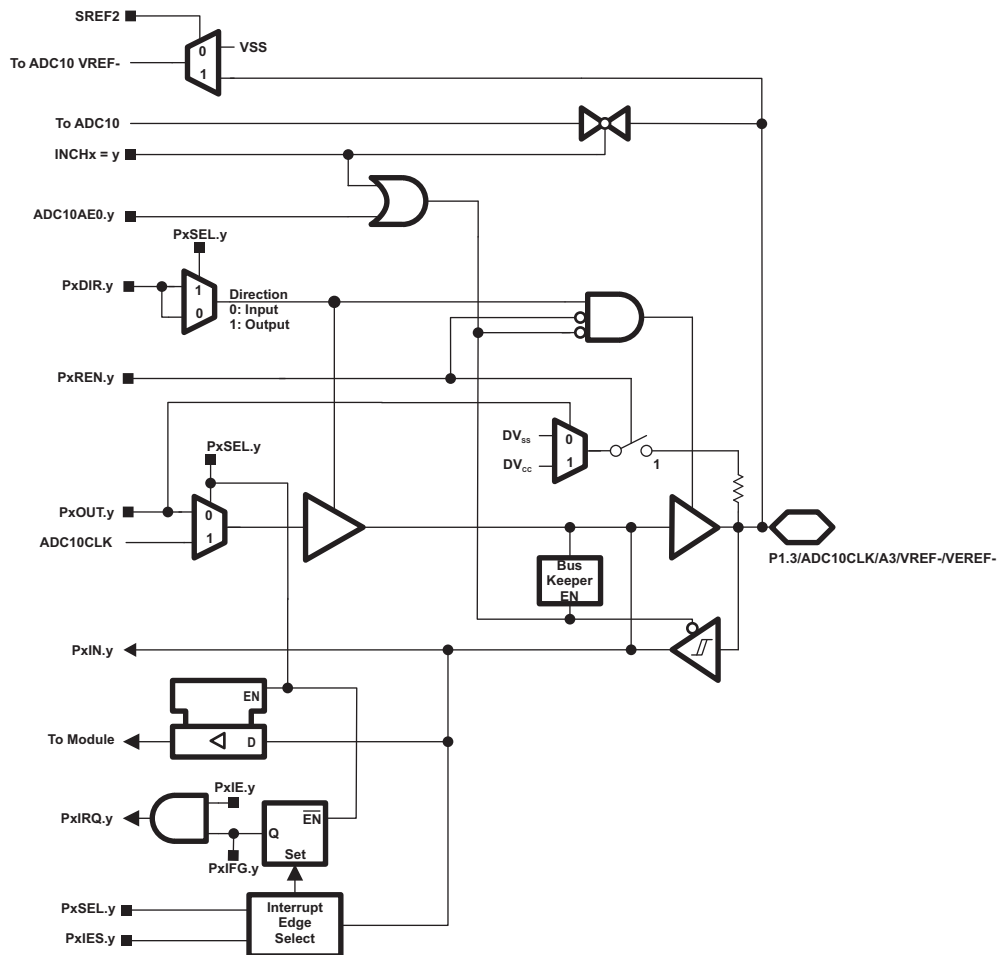


Table 14. Port P1 (P1.3) Pin Functions

PIN NAME (P1.x)	x	FUNCTION	CONTROL BITS OR SIGNALS		
			P1DIR.x	P1SEL.x	ADC10AE.x (INCH.x = 1)
P1.3/ ADC10CLK/ A3/ VREF-/ VEREF-	3	P1.x (I/O)	I: 0; O: 1	0	0
		ADC10CLK	1	1	0
		A3	X	X	1 (y = 3)
		VREF-	X	X	1
		VEREF-	X	X	1

10.3 Port P1 Pin Schematic: P1.4, Input/Output With Schmitt Trigger

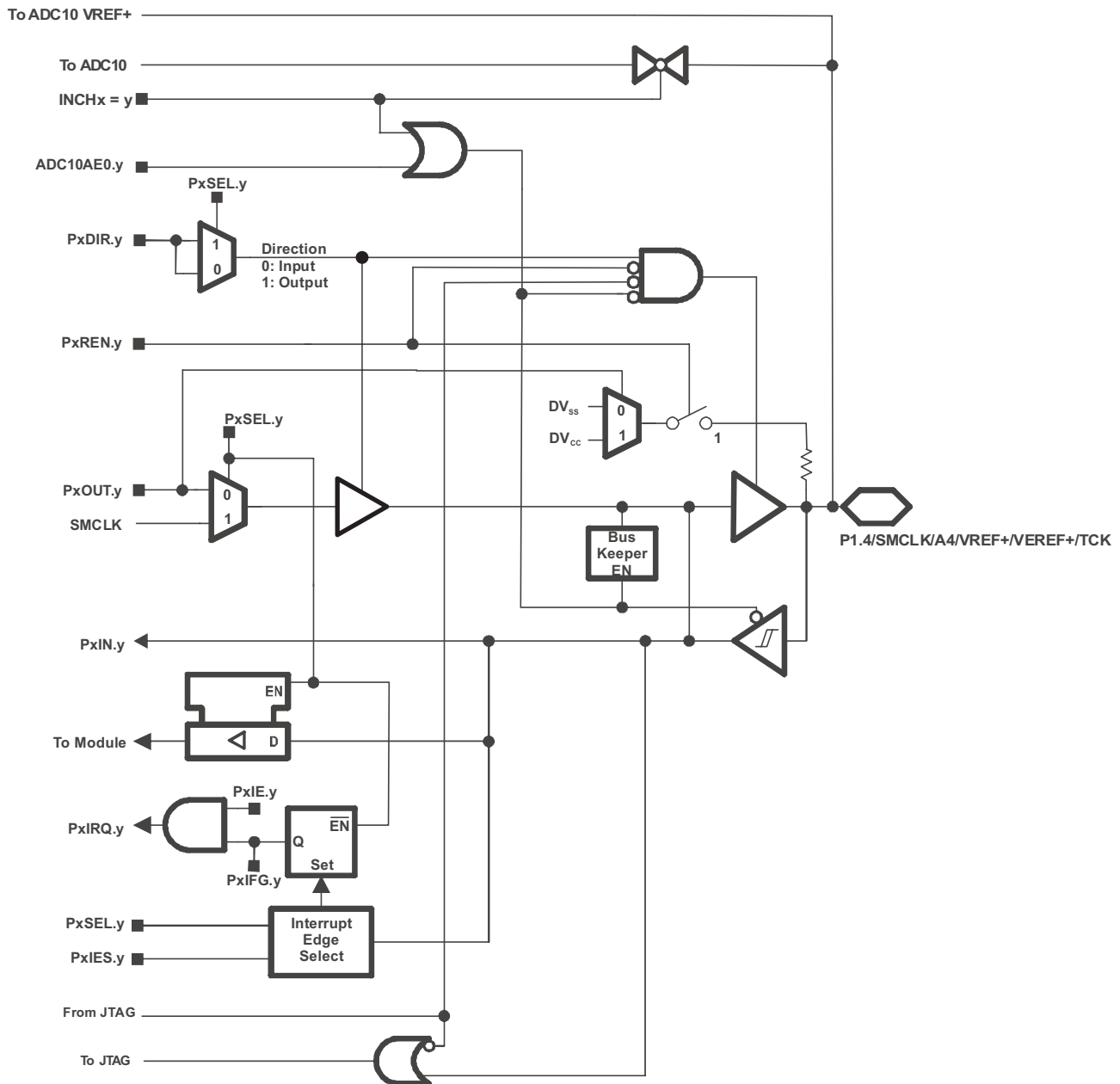


Table 15. Port P1 (P1.4) Pin Functions

PIN NAME (P1.x)	x	FUNCTION	CONTROL BITS OR SIGNALS			
			P1DIR.x	P1SEL.x	ADC10AE.x (INCH.x = 1)	JTAG Mode
P1.4/ SMCLK/ A4/ VREF+/ VEREF+/ TCK	4	P1.x (I/O)	I: 0; O: 1	0	0	0
		SMCLK	1	1	0	0
		A4	X	X	1 (y = 4)	0
		VREF+	X	X	1	0
		VEREF+	X	X	1	0
		TCK	X	X	0	1

10.4 Port P1 Pin Schematic: P1.5, Input/Output With Schmitt Trigger

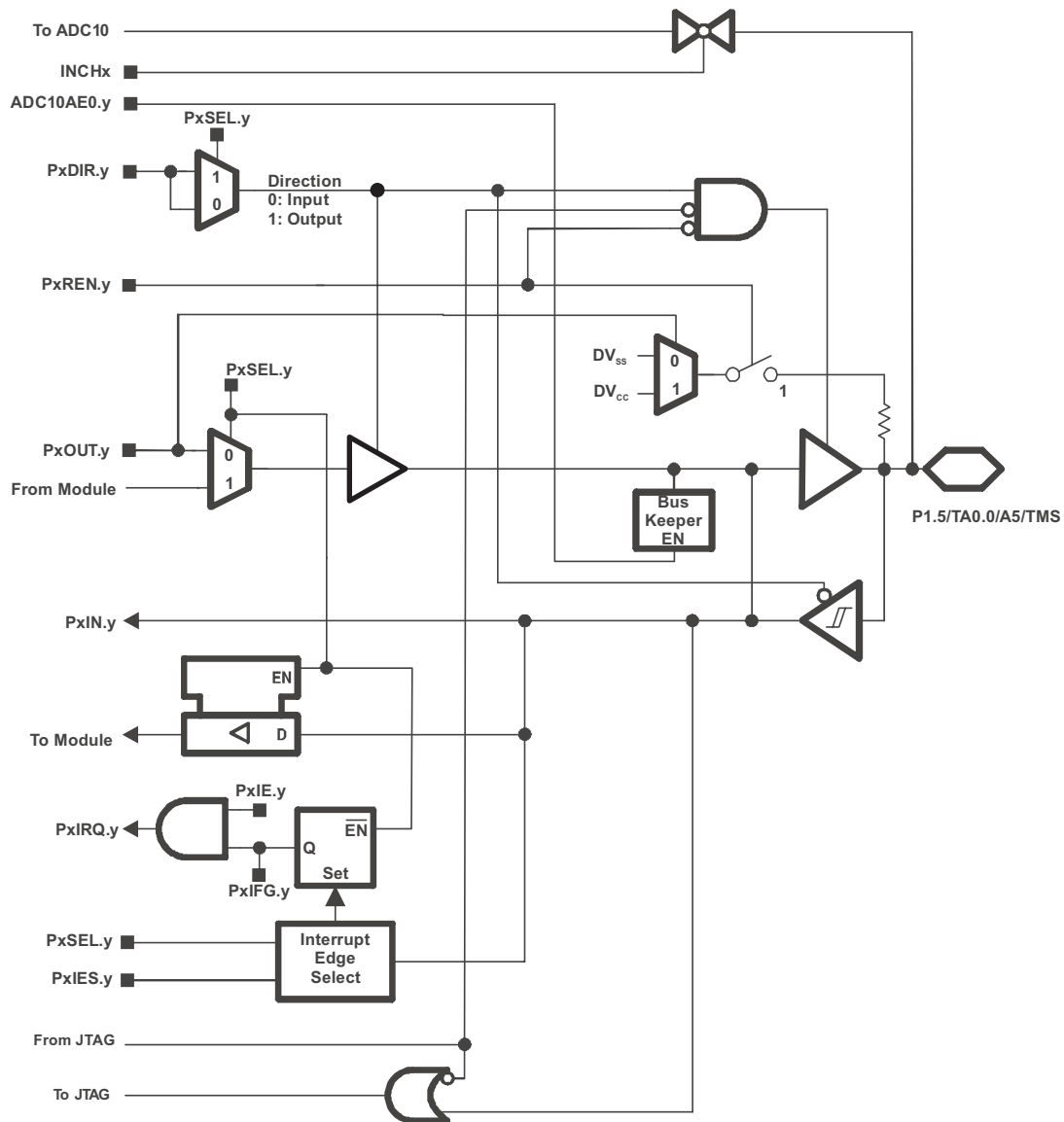
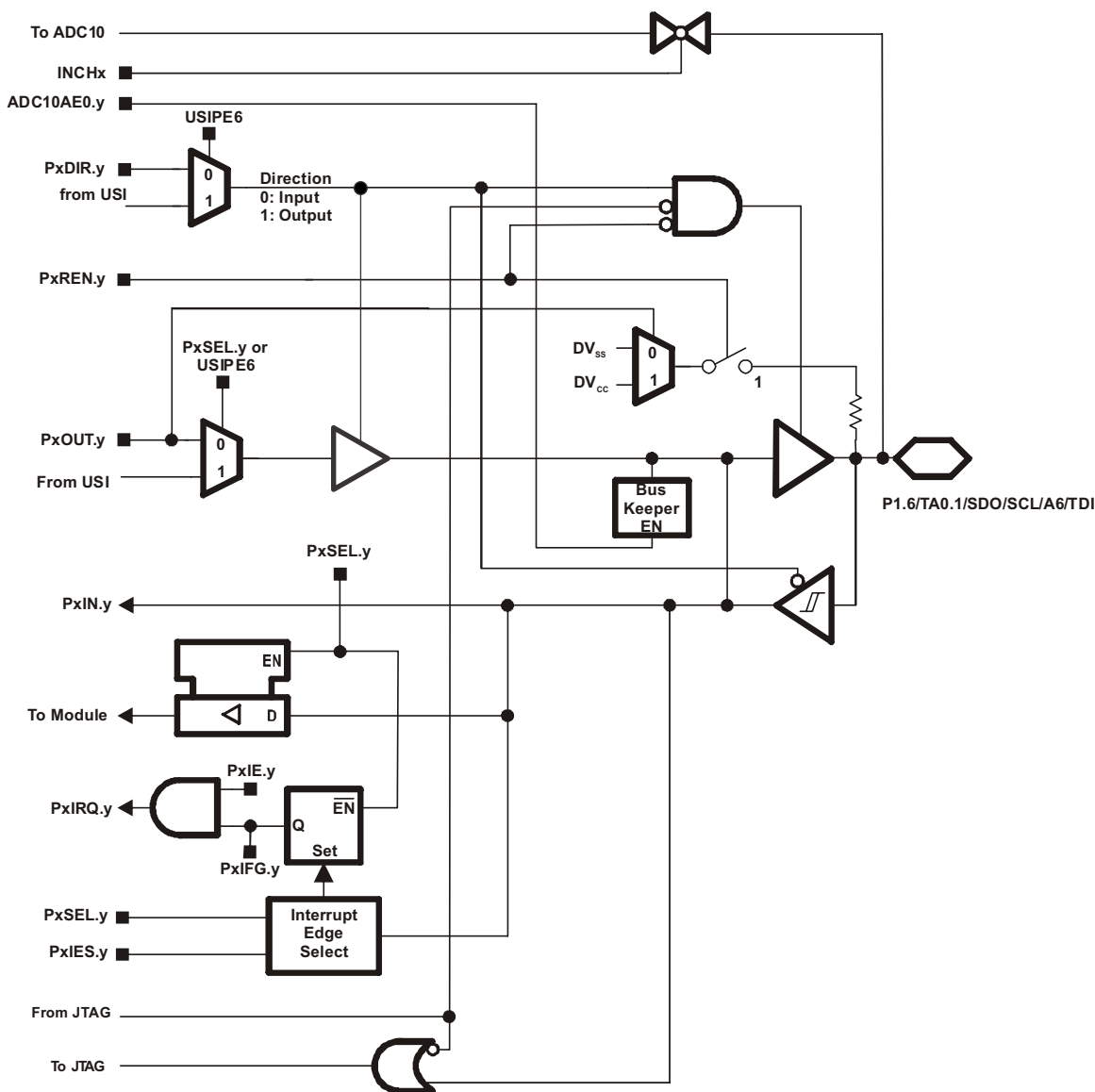


Table 16. Port P1 (P1.5) Pin Functions

PIN NAME (P1.x)	x	FUNCTION	CONTROL BITS OR SIGNALS				
			P1DIR.x	P1SEL.x	USIP.x	ADC10AE.x (INCH.x = 1)	JTAG Mode
P1.5/ TA0.0/ A5/ SCLK/ TMS	5	P1.x (I/O)	I: 0; O: 1	0	0	0	0
		TA0.0	1	1	0	0	0
		A5	X	X	X	1 (y = 5)	0
		SCLK	X	X	1	0	0
		TMS	X	X	0	0	1

10.5 Port P1 Pin Schematic: P1.6, Input/Output With Schmitt Trigger

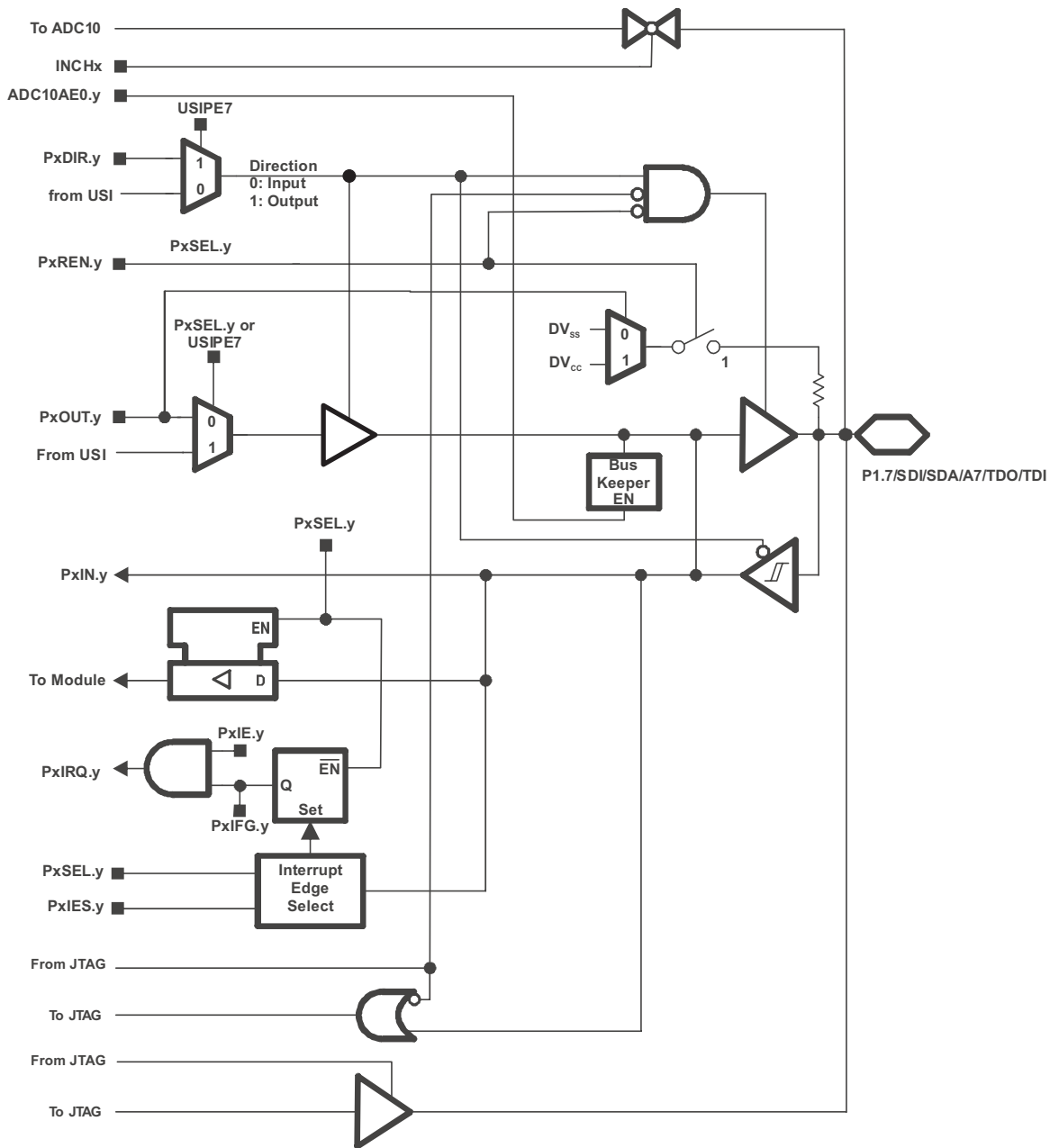


USI in I2C mode: Output driver drives low level only. Driver is disabled in JTAG mode.

Table 17. Port P1 (P1.6) Pin Functions

PIN NAME (P1.x)	x	FUNCTION	CONTROL BITS OR SIGNALS				
			P1DIR.x	P1SEL.x	USIP.x	ADC10AE.x (INCH.x = 1)	JTAG Mode
P1.6/ TA0.1/	6	P1.x (I/O)	I: 0; O: 1	0	0	0	0
		TA0.1	1	1	0	0	0
		TA0.CCR1B	0	1	0	0	0
A6/		A6	X	X	0	1 (y = 6)	0
SDO/		SDO	X	X	1	0	0
TDI/TCLK		TDI/TCLK	X	X	0	0	1

10.6 Port P1 Pin Schematic: P1.7, Input/Output With Schmitt Trigger



USI in I2C mode: Output driver drives low level only. Driver is disabled in JTAG mode.

Table 18. Port P1 (P1.7) Pin Functions

PIN NAME (P1.x)	x	FUNCTION	CONTROL BITS OR SIGNALS				
			P1DIR.x	P1SEL.x	USIP.x	ADC10AE.x (INCH.x = 1)	JTAG Mode
P1.7/ A7/ SDI/SDO TDO/TDI	7	P1.x (I/O)	I: 0; O: 1	0	0	0	0
		A7	X	X	0	1 (y = 7)	0
		SDI/SDO	X	X	1	0	0
		TDO/TDI	X	X	0	0	1

10.7 Port P2 Pin Schematic: P2.6, Input/Output With Schmitt Trigger

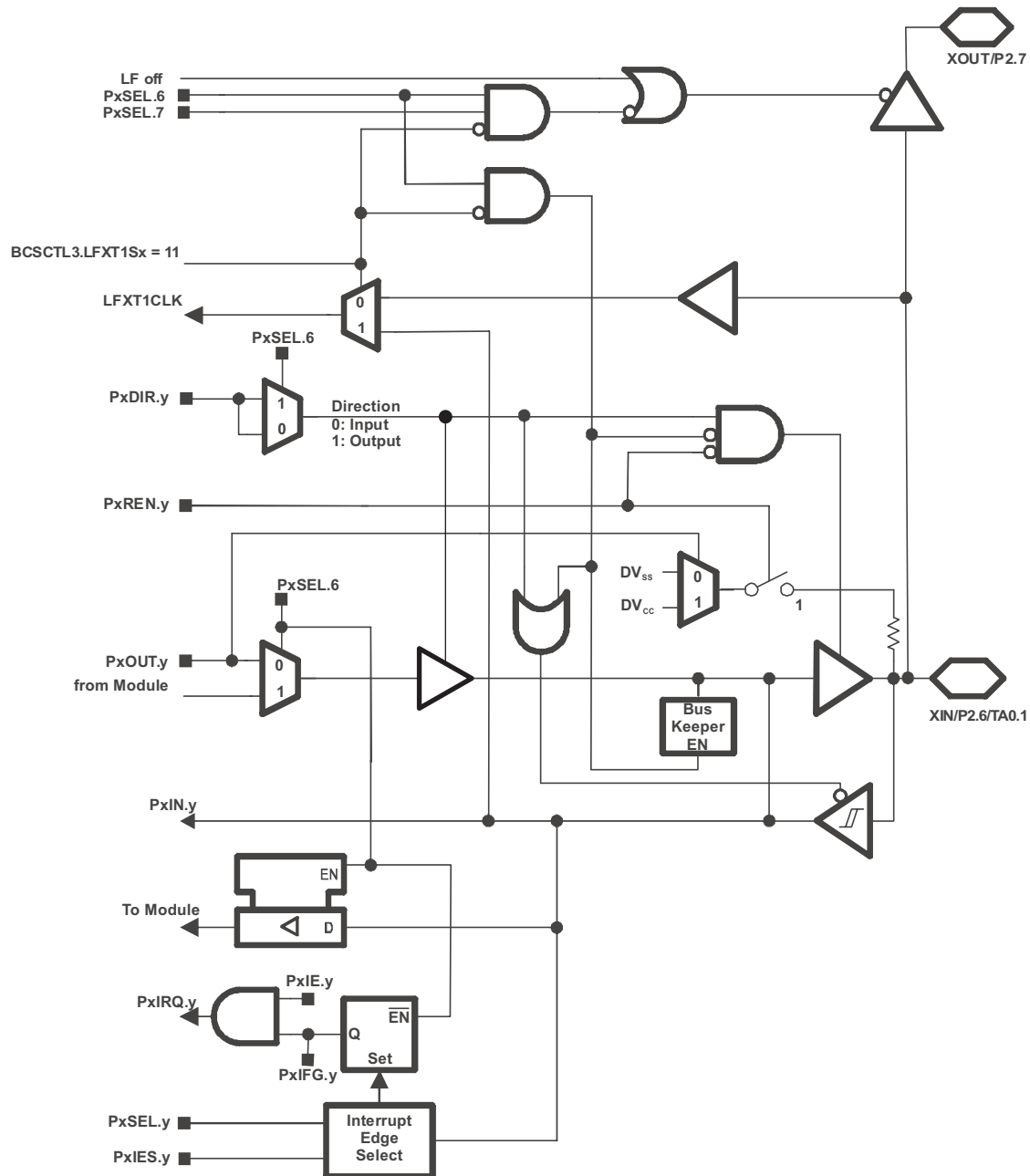


Table 19. Port P2 (P2.6) Pin Functions

PIN NAME (P2.x)	x	FUNCTION	CONTROL BITS OR SIGNALS		
			P2DIR.x	P2SEL.6	P2SEL.7
XIN	6	XIN	0	1	1
P2.6		P2.x (I/O)	I: 0; O: 1	0	X
TA0.1		TA0.1 ⁽¹⁾	1	1	X

(1) BCSTCL3.LFXT1Sx = 11 is required.

10.8 Port P2 Pin Schematic: P2.7, Input/Output With Schmitt Trigger

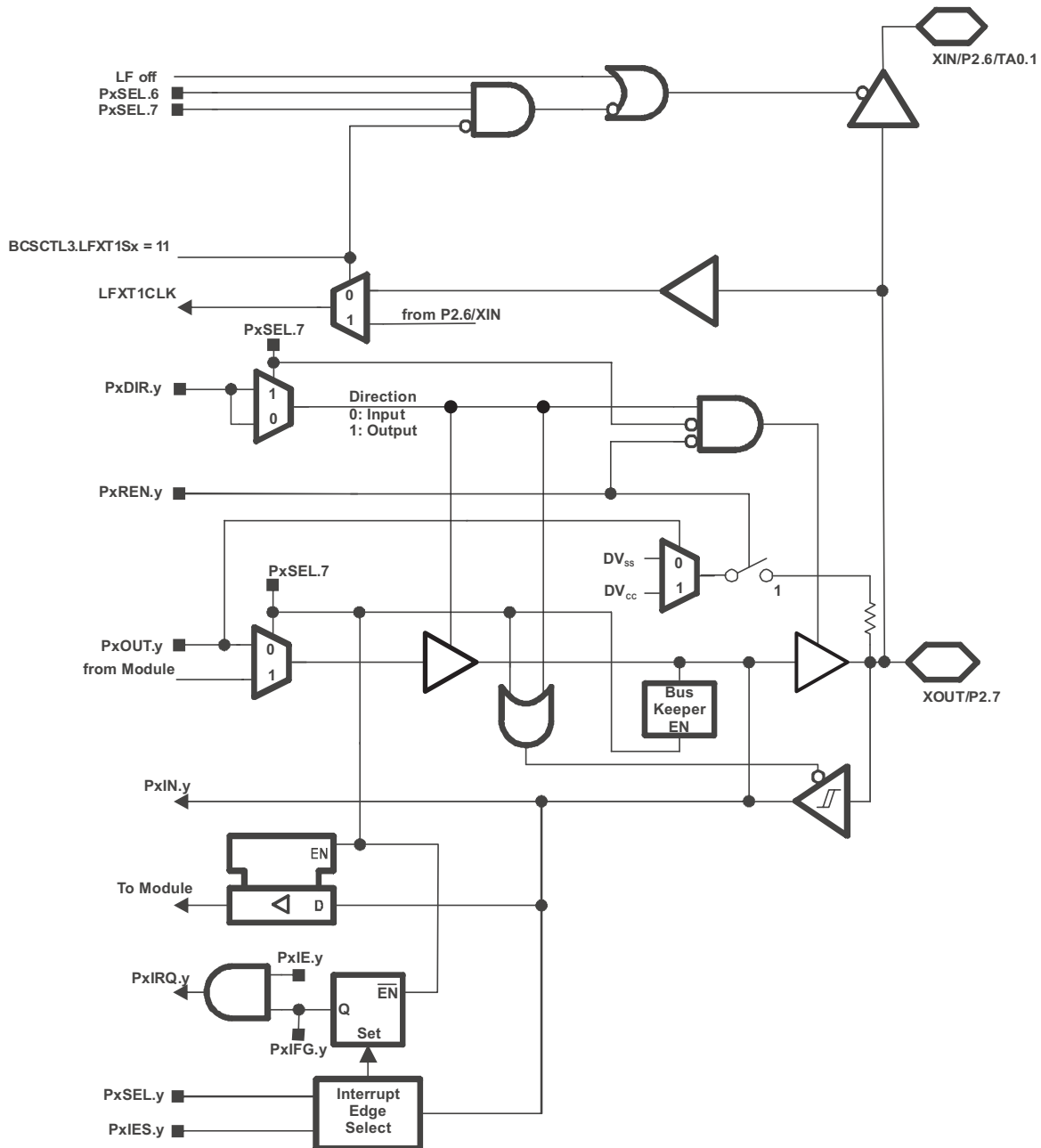


Table 20. Port P2 (P2.7) Pin Functions

PIN NAME (P2.x)	x	FUNCTION	CONTROL BITS OR SIGNALS		
			P2DIR.x	P2SEL.6	P2SEL.7
XOUT P2.7	7	XOUT	1	1	1
		P2.x (I/O)	I: 0; O: 1	X	0

11 器件和文档支持

11.1 器件支持

11.1.1 Development Tools Support

All MSP430™ microcontrollers are supported by a wide variety of software and hardware development tools. Tools are available from TI and various third parties. See them all at www.ti.com/msp430tools.

11.1.1.1 Hardware Features

See the *Code Composer Studio for MSP430 User's Guide* (SLAU157) for details on the available features.

MSP430 Architecture	4-Wire JTAG	2-Wire JTAG	Break-points (N)	Range Break-points	Clock Control	State Sequencer	Trace Buffer	LPMx.5 Debugging Support
MSP430	Yes	Yes	2	No	Yes	No	No	No

11.1.1.2 Recommended Hardware Options

11.1.1.2.1 Target Socket Boards

The target socket boards allow easy programming and debugging of the device using JTAG. They also feature header pin outs for prototyping. Target socket boards are orderable individually or as a kit with the JTAG programmer and debugger included. The following table shows the compatible target boards and the supported packages.

Package	Target Board and Programmer Bundle	Target Board Only
14-pin TSSOP (PW)	MSP-FET430U14	MSP-TS430PW14
	MSP-FET430U28A	MSP-TS430PW28A

11.1.1.2.2 Experimenter Boards

Experimenter Boards and Evaluation kits are available for some MSP430 devices. These kits feature additional hardware components and connectivity for full system evaluation and prototyping. See www.ti.com/msp430tools for details.

11.1.1.2.3 Debugging and Programming Tools

Hardware programming and debugging tools are available from TI and from its third party suppliers. See the full list of available tools at www.ti.com/msp430tools.

11.1.1.2.4 Production Programmers

The production programmers expedite loading firmware to devices by programming several devices simultaneously.

Part Number	PC Port	Features	Provider
MSP-GANG	Serial and USB	Program up to eight devices at a time. Works with PC or standalone.	Texas Instruments

11.1.1.3 Recommended Software Options

11.1.1.3.1 Integrated Development Environments

Software development tools are available from TI or from third parties. Open source solutions are also available. This device is supported by Code Composer Studio™ IDE (CCS).

11.1.1.3.2 MSP430Ware

[MSP430Ware](#) is a collection of code examples, data sheets, and other design resources for all MSP430 devices delivered in a convenient package. MSP430Ware is available as a component of CCS or as a standalone package.

11.1.1.3.3 Command-Line Programmer

MSP430 Flasher is an open-source, shell-based interface for programming MSP430 microcontrollers through a FET programmer or eZ430 using JTAG or Spy-Bi-Wire (SBW) communication. MSP430 Flasher can be used to download binary files (.txt or .hex) files directly to the MSP430 Flash without the need for an IDE.

11.1.1.4 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

[TI E2E Community](#)

TI's Engineer-to-Engineer (E2E) Community. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas, and help solve problems with fellow engineers.

[TI Embedded Processors Wiki](#)

Texas Instruments Embedded Processors Wiki. Established to help developers get started with embedded processors from Texas Instruments and to foster innovation and growth of general knowledge about the hardware and software surrounding these devices.

11.1.2 Device and Development Tool Nomenclature

To designate the stages in the product development cycle, TI assigns prefixes to the part numbers of all MSP430™ MCU devices and support tools. Each MSP430™ MCU commercial family member has one of three prefixes: MSP, PMS, or XMS (for example, MSP430F5259). Texas Instruments recommends two of three possible prefix designators for its support tools: MSP and MSPX. These prefixes represent evolutionary stages of product development from engineering prototypes (with XMS for devices and MSPX for tools) through fully qualified production devices and tools (with MSP for devices and MSP for tools).

Device development evolutionary flow:

XMS – Experimental device that is not necessarily representative of the final device's electrical specifications

PMS – Final silicon die that conforms to the device's electrical specifications but has not completed quality and reliability verification

MSP – Fully qualified production device

Support tool development evolutionary flow:

MSPX – Development-support product that has not yet completed Texas Instruments internal qualification testing.

MSP – Fully-qualified development-support product

XMS and PMS devices and MSPX development-support tools are shipped against the following disclaimer:

"Developmental product is intended for internal evaluation purposes."

MSP devices and MSP development-support tools have been characterized fully, and the quality and reliability of the device have been demonstrated fully. TI's standard warranty applies.

Predictions show that prototype devices (XMS and PMS) have a greater failure rate than the standard production devices. Texas Instruments recommends that these devices not be used in any production system because their expected end-use failure rate still is undefined. Only qualified production devices are to be used.

TI device nomenclature also includes a suffix with the device family name. This suffix indicates the package type (for example, PZP) and temperature range (for example, T). [Figure 17](#) provides a legend for reading the complete device name for any family member.

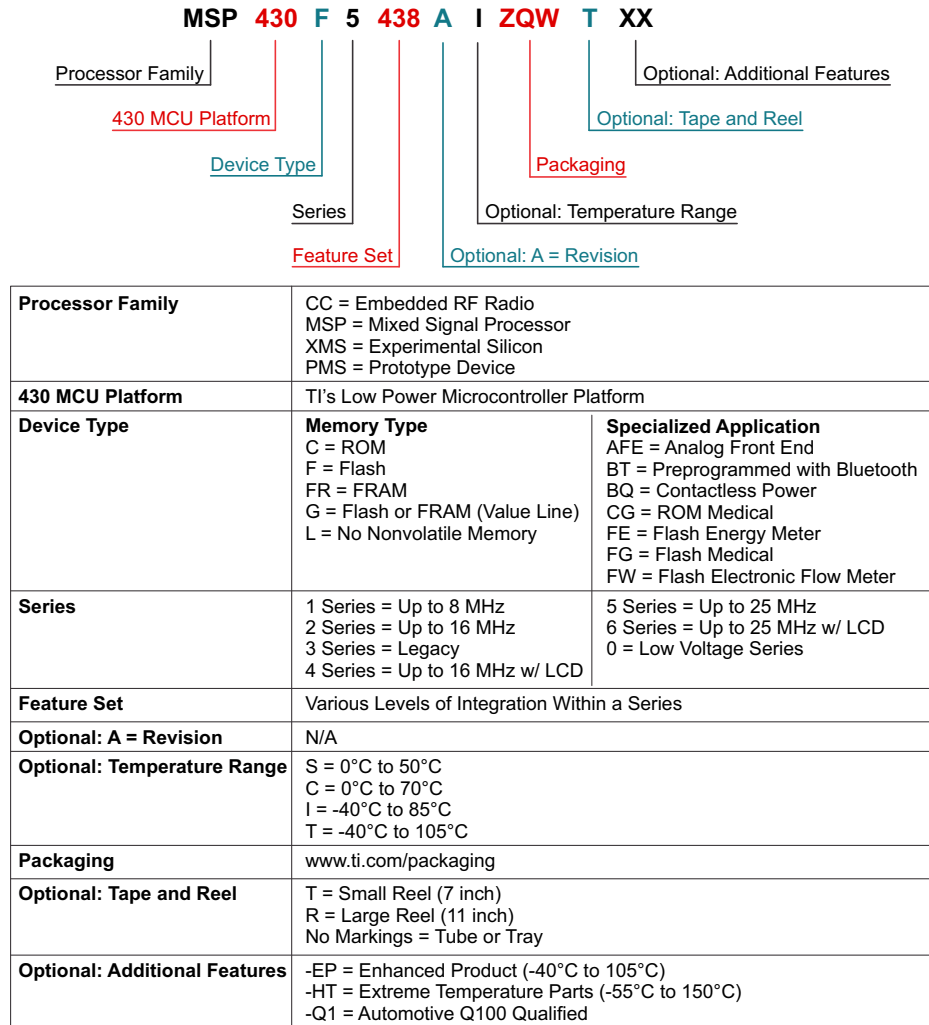


图 17. Device Nomenclature

11.2 文档支持

11.2.1 相关文档

以下文档描述了 MSP430G2231 器件。在 www.ti.com 内提供这些文档的副本。

SLAU144 《MSP430x2xx 系列用户指南》。在这个器件系列中提供模块和外设相关的详细信息。

SLAZ417 **MSP430G2231** 器件勘误表。描述了针对 MSP430G2231 器件功能技术规格的已知例外情况。

11.3 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E Community

TI's *Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas, and help solve problems with fellow engineers.

TI Embedded Processors Wiki

Community Resources (接下页)

Texas Instruments Embedded Processors Wiki. Established to help developers get started with embedded processors from Texas Instruments and to foster innovation and growth of general knowledge about the hardware and software surrounding these devices.

11.4 商标

MSP430, Code Composer Studio are trademarks of Texas Instruments.
All other trademarks are the property of their respective owners.

11.5 静电放电警告



这些装置包含有限的内置 ESD 保护。存储或装卸时，应将导线一起截短或将装置放置于导电泡棉中，以防止 MOS 门极遭受静电损伤。

11.6 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms and definitions.

12 机械封装和可订购信息

以下页中包括机械封装和可订购信息。 这些信息是针对指定器件可提供的最新数据。 这些数据会在无通知且不对本文档进行修订的情况下发生改变。 欲获得该数据表的浏览器版本，请查阅左侧的导航栏。

重要声明

德州仪器(TI) 及其下属子公司有权根据 JESD46 最新标准, 对所提供的产品和服务进行更正、修改、增强、改进或其它更改, 并有权根据 JESD48 最新标准中止提供任何产品和服务。客户在下订单前应获取最新的相关信息, 并验证这些信息是否完整且是最新的。所有产品的销售都遵循在订单确认时所提供的TI 销售条款与条件。

TI 保证其所销售的组件的性能符合产品销售时 TI 半导体产品销售条件与条款的适用规范。仅在 TI 保证的范围内, 且 TI 认为 有必要时才会使用测试或其它质量控制技术。除非适用法律做出了硬性规定, 否则没有必要对每种组件的所有参数进行测试。

TI 对应用帮助或客户产品设计不承担任何义务。客户应对其使用 TI 组件的产品和应用自行负责。为尽量减小与客户产品和应用相关的风险, 客户应提供充分的设计与操作安全措施。

TI 不对任何 TI 专利权、版权、屏蔽作品权或其它与使用了 TI 组件或服务的组合设备、机器或流程相关的 TI 知识产权中授予 的直接或隐含权限作出任何保证或解释。TI 所发布的与第三方产品或服务有关的信息, 不能构成从 TI 获得使用这些产品或服务 的许可、授权、或认可。使用此类信息可能需要获得第三方的专利权或其它知识产权方面的许可, 或是 TI 的专利权或其它 知识产权方面的许可。

对于 TI 的产品手册或数据表中 TI 信息的重要部分, 仅在没有对内容进行任何篡改且带有相关授权、条件、限制和声明的情况 下才允许进行复制。TI 对此类篡改过的文件不承担任何责任或义务。复制第三方的信息可能需要服从额外的限制条件。

在转售 TI 组件或服务时, 如果对该组件或服务参数的陈述与 TI 标明的参数相比存在差异或虚假成分, 则会失去相关 TI 组件 或服务的所有明示或暗示授权, 且这是不正当的、欺诈性商业行为。TI 对任何此类虚假陈述均不承担任何责任或义务。

客户认可并同意, 尽管任何应用相关信息或支持仍可能由 TI 提供, 但他们将独力负责满足与其产品及其在应用中使用的 TI 产品 相关的所有法律、法规和安全相关要求。客户声明并同意, 他们具备制定与实施安全措施所需的全部专业技术和知识, 可预见 故障的危险后果、监测故障及其后果、降低有可能造成人身伤害的故障的发生机率并采取适当的补救措施。客户将全额赔偿因 在此类安全关键应用中使用任何 TI 组件而对 TI 及其代理造成的任何损失。

在某些场合中, 为了推进安全相关应用有可能对 TI 组件进行特别的促销。TI 的目标是利用此类组件帮助客户设计和创立其特 有的可满足适用的功能安全性标准和要求的终端产品解决方案。尽管如此, 此类组件仍然服从这些条款。

TI 组件未获得用于 FDA Class III (或类似的生命攸关医疗设备) 的授权许可, 除非各方授权官员已经达成了专门管控此类使 用的特别协议。

只有那些 TI 特别注明属于军用等级或“增强型塑料”的 TI 组件才是设计或专门用于军事/航空应用或环境的。购买者认可并同 意, 对并非指定面向军事或航空航天用途的 TI 组件进行军事或航空航天方面的应用, 其风险由客户单独承担, 并且由客户独 力负责满足与此类使用相关的所有法律和法规要求。

TI 已明确指定符合 ISO/TS16949 要求的产品, 这些产品主要用于汽车。在任何情况下, 因使用非指定产品而无法达到 ISO/TS16949 要求, TI 不承担任何责任。

	产品		应用
数字音频	www.ti.com.cn/audio	通信与电信	www.ti.com.cn/telecom
放大器和线性器件	www.ti.com.cn/amplifiers	计算机及周边	www.ti.com.cn/computer
数据转换器	www.ti.com.cn/dataconverters	消费电子	www.ti.com.cn/consumer-apps
DLP® 产品	www.dlp.com	能源	www.ti.com.cn/energy
DSP - 数字信号处理器	www.ti.com.cn/dsp	工业应用	www.ti.com.cn/industrial
时钟和计时器	www.ti.com.cn/clockandtimers	医疗电子	www.ti.com.cn/medical
接口	www.ti.com.cn/interface	安防应用	www.ti.com.cn/security
逻辑	www.ti.com.cn/logic	汽车电子	www.ti.com.cn/automotive
电源管理	www.ti.com.cn/power	视频和影像	www.ti.com.cn/video
微控制器 (MCU)	www.ti.com.cn/microcontrollers		
RFID 系统	www.ti.com.cn/rfidsys		
OMAP应用处理器	www.ti.com.cn/omap		
无线连通性	www.ti.com.cn/wirelessconnectivity	德州仪器在线技术支持社区	www.deyisupport.com

邮寄地址: 上海市浦东新区世纪大道1568号, 中建大厦32楼邮政编码: 200122
Copyright © 2015, 德州仪器半导体技术(上海)有限公司

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
MSP430G2231IPW4RQ1	ACTIVE	TSSOP	PW	14	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	G2231Q1	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF MSP430G2231-Q1 :

- Catalog: [MSP430G2231](#)
- Enhanced Product: [MSP430G2231-EP](#)

NOTE: Qualified Version Definitions:

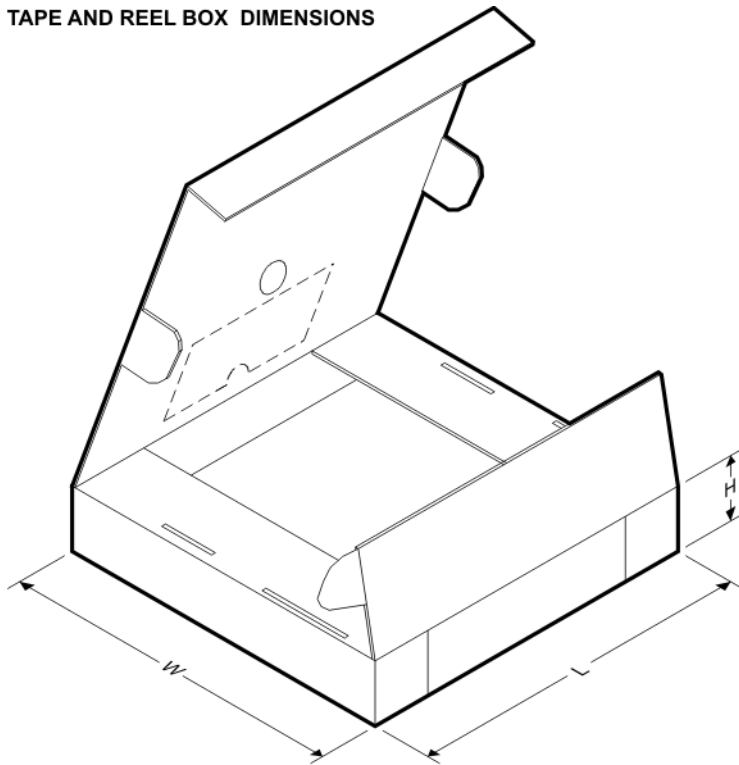
- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MSP430G2231IPW4RQ1	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

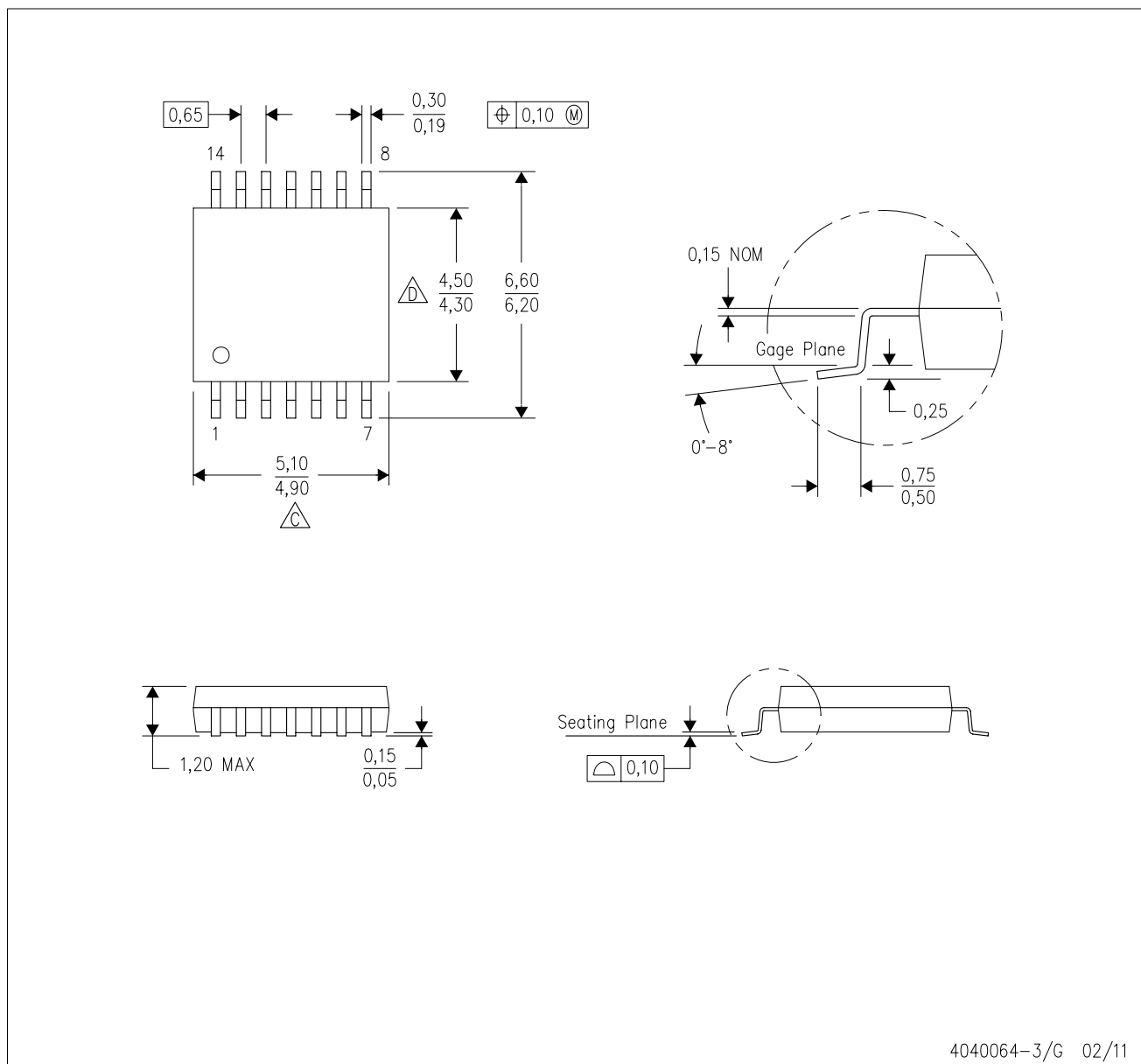


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MSP430G2231IPW4RQ1	TSSOP	PW	14	2000	853.0	449.0	35.0

PW (R-PDSO-G14)

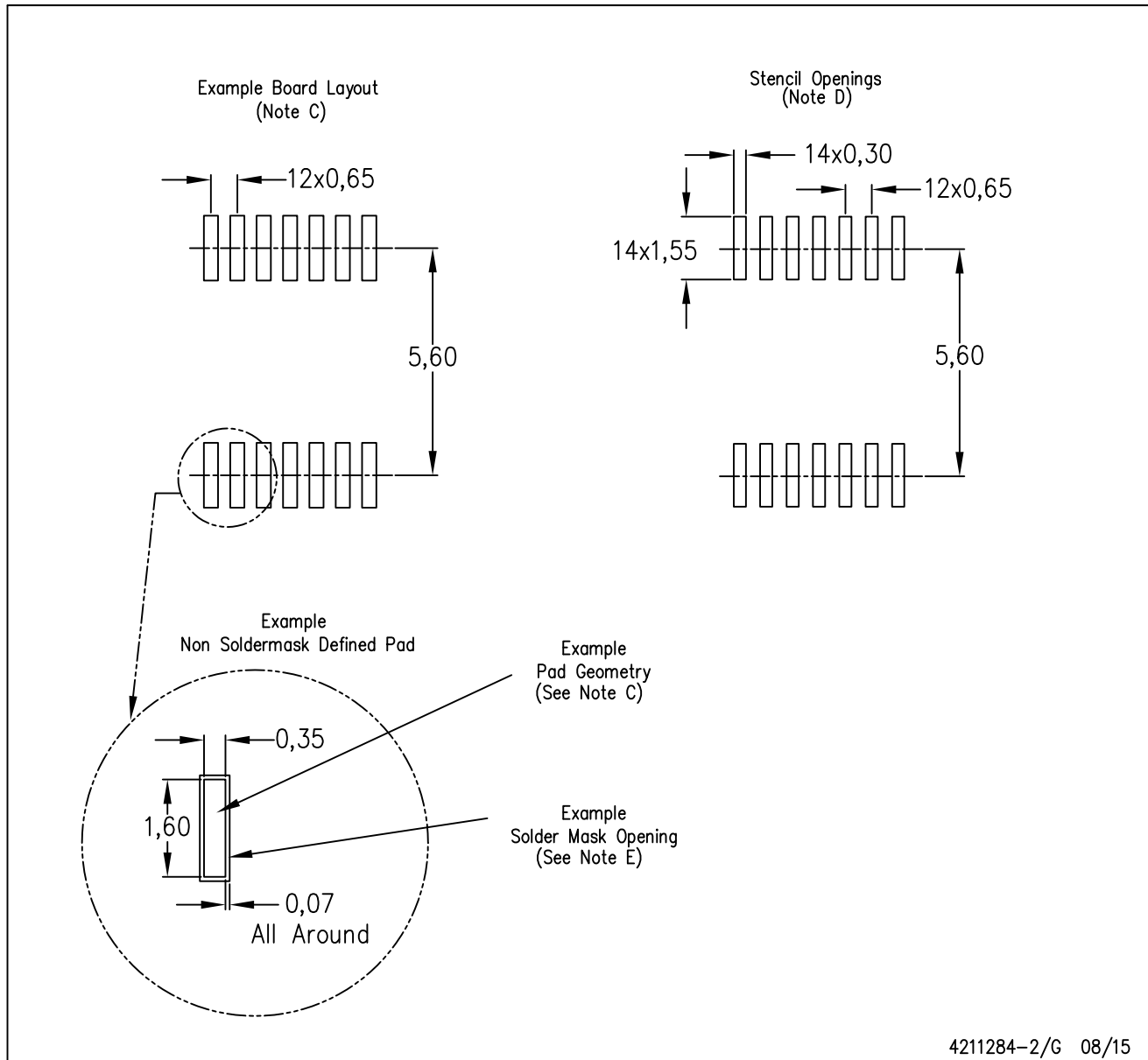
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

重要声明和免责声明

TI 均以“原样”提供技术性 & 可靠性数据（包括数据表）、设计资源（包括参考设计）、应用或其他设计建议、网络工具、安全信息和其他资源，不保证其中不含任何瑕疵，且不做任何明示或暗示的担保，包括但不限于对适销性、适合某特定用途或不侵犯任何第三方知识产权的暗示担保。

所述资源可供专业开发人员应用 TI 产品进行设计使用。您将对以下行为独自承担全部责任：(1) 针对您的应用选择合适的 TI 产品；(2) 设计、验证并测试您的应用；(3) 确保您的应用满足相应标准以及任何其他安全、安保或其他要求。所述资源如有变更，恕不另行通知。TI 对您使用所述资源的授权仅限于开发资源所涉及 TI 产品的相关应用。除此之外不得复制或展示所述资源，也不提供其它 TI 或任何第三方的知识产权授权许可。如因使用所述资源而产生任何索赔、赔偿、成本、损失及债务等，TI 对此概不负责，并且您须赔偿由此对 TI 及其代表造成的损害。

TI 所提供产品均受 TI 的销售条款 (<http://www.ti.com.cn/zh-cn/legal/termsofsale.html>) 以及 [ti.com.cn](http://www.ti.com.cn) 上或随附 TI 产品提供的其他可适用条款的约束。TI 提供所述资源并不扩展或以其他方式更改 TI 针对 TI 产品所发布的可适用的担保范围或担保免责声明。

邮寄地址：上海市浦东新区世纪大道 1568 号中建大厦 32 楼，邮政编码：200122
Copyright © 2020 德州仪器半导体技术（上海）有限公司